

AD7569/AD7669

FEATURES

- 2 μ s ADC with Track/Hold
- 1 μ s DAC with Output Amplifier
- AD7569, Single DAC Output
- AD7669, Dual DAC Output
- On-Chip Bandgap Reference
- Fast Bus Interface
- Single or Dual 5 V Supplies

GENERAL DESCRIPTION

The AD7569/AD7669 is a complete, 8-bit, analog I/O system on a single monolithic chip. The AD7569 contains a high speed successive approximation ADC with 2 μ s conversion time, a track/hold with 200 kHz bandwidth, a DAC and an output buffer amplifier with 1 μ s settling time. A temperature-compensated 1.25 V bandgap reference provides a precision reference voltage for the ADC and the DAC. The AD7669 is similar, but contains two DACs with output buffer amplifiers.

A choice of analog input/output ranges is available. Using a supply voltage of +5 V, input and output ranges of zero to 1.25 V and zero to 2.5 volts may be programmed using the RANGE input pin. Using a ± 5 V supply, bipolar ranges of ± 1.25 V or ± 2.5 V may be programmed.

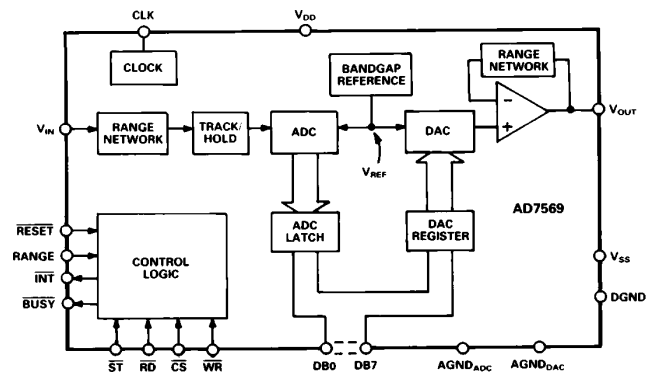
Digital interfacing is via an 8-bit I/O port and standard microprocessor control lines. Bus interface timing is extremely fast, allowing easy connection to all popular 8-bit microprocessors. A separate start convert line controls the track/hold and ADC to give precise control of the sampling period.

The AD7569/AD7669 is fabricated in Linear-Compatible CMOS (LC²MOS), an advanced, mixed technology process combining precision bipolar circuits with low power CMOS logic. The AD7569 is packaged in a 24-pin, 0.3" wide "skinny" DIP, a 24-terminal SOIC and 28-terminal PLCC and LCCC packages. The AD7669 is available in a 28-pin, 0.6" plastic DIP, 28-terminal SOIC and 28-terminal PLCC package.

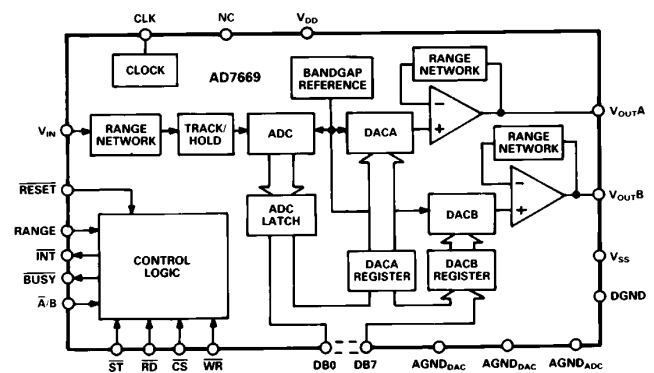
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AD7569 FUNCTIONAL BLOCK DIAGRAM



AD7669 FUNCTIONAL BLOCK DIAGRAM



PRODUCT HIGHLIGHTS

1. Complete Analog I/O on a Single Chip.
The AD7569/AD7669 provides everything necessary to interface a microprocessor to the analog world. No external components or user trims are required and the overall accuracy of the system is tightly specified, eliminating the need to calculate error budgets from individual component specifications.
2. Dynamic Specifications for DSP Users.
In addition to the traditional ADC and DAC specifications, the AD7569/AD7669 is specified for ac parameters, including signal-to-noise ratio, distortion and input bandwidth.
3. Fast Microprocessor Interface.
The AD7569/AD7669 has bus interface timing compatible with all modern microprocessors, with bus access and relinquish times less than 75 ns and write pulse width less than 80 ns.

AD7569/AD7669—SPECIFICATIONS

DAC SPECIFICATIONS¹ ($V_{DD} = +5\text{ V} \pm 5\%$; $V_{SS}^2 = \text{RANGE} = \text{AGND}_{\text{DAC}} = \text{AGND}_{\text{ADC}} = \text{DGND} = 0\text{ V}$; $R_L = 2\text{ k}\Omega$, $C_L = 100\text{ pF}$ to AGND_{DAC} unless otherwise noted. All specifications T_{MIN} to T_{MAX} unless otherwise noted.)

Parameter	AD7569 J, A Versions ³ AD7669 J Version	AD7569 K, B Versions	AD7569 S Version	AD7569 T Version	Units	Conditions/Comments
STATIC PERFORMANCE						
Resolution ⁴	8	8	8	8	Bits	
Total Unadjusted Error ⁵	± 2	± 2	± 3	± 3	LSB typ	
Relative Accuracy ⁵	± 1	$\pm 1/2$	± 1	$\pm 1/2$	LSB max	
Differential Nonlinearity ⁵	± 1	$\pm 3/4$	± 1	$\pm 3/4$	LSB max	Guaranteed Monotonic
Unipolar Offset Error @ +25°C	± 2	± 1.5	± 2	± 1.5	LSB max	DAC data is all 0s; $V_{SS} = 0\text{ V}$
T_{MIN} to T_{MAX}	± 2.5	± 2	± 2.5	± 2	LSB max	Typical tempo is 10 $\mu\text{V}/^\circ\text{C}$ for +1.25 V range
Bipolar Zero Offset Error @ +25°C	± 2	± 1.5	± 2	± 1.5	LSB max	DAC data is all 0s; $V_{SS} = -5\text{ V}$
T_{MIN} to T_{MAX}	± 2.5	± 2	± 2.5	± 2	LSB max	Typical tempo is 20 $\mu\text{V}/^\circ\text{C}$ for $\pm 1.25\text{ V}$ range
Full-Scale Error ⁶ (AD7569 Only) @ +25°C	± 2	± 1	± 2	± 1	LSB max	$V_{DD} = 5\text{ V}$
T_{MIN} to T_{MAX}	± 3	± 2	± 4	± 3	LSB max	
Full-Scale Error ⁶ (AD7669 Only) @ +25°C	± 3				LSB max	$V_{DD} = 5\text{ V}$
T_{MIN} to T_{MAX}	± 4.5				LSB max	
DACA/DACB Full-Scale Error Match ⁶ (AD7669 Only)	± 2.5				LSB max	$V_{DD} = 5\text{ V}$
$\Delta\text{Full Scale}/\Delta V_{DD}$, $T_A = +25^\circ\text{C}$	0.5	0.5	0.5	0.5	LSB max	$V_{\text{OUT}} = 2.5\text{ V}$; $\Delta V_{DD} = \pm 5\%$
$\Delta\text{Full Scale}/\Delta V_{SS}$, $T_A = +25^\circ\text{C}$	0.5	0.5	0.5	0.5	LSB max	$V_{\text{OUT}} = -2.5\text{ V}$; $\Delta V_{SS} = \pm 5\%$
Load Regulation at Full Scale	0.2	0.2	0.2	0.2	LSB max	$R_L = 2\text{ k}\Omega$ to $^\circ\text{C}$
DYNAMIC PERFORMANCE						
Signal-to-Noise Ratio ⁵ (SNR)	44	46	44	46	dB min	$V_{\text{OUT}} = 20\text{ kHz}$ full-scale sine wave with $f_{\text{SAMPLING}} = 400\text{ kHz}$
Total Harmonic Distortion ⁵ (THD)	48	48	48	48	dB max	$V_{\text{OUT}} = 20\text{ kHz}$ full-scale sine wave with $f_{\text{SAMPLING}} = 400\text{ kHz}$
Intermodulation Distortion ⁵ (IMD)	55	55	55	55	dB typ	$f_a = 18.4\text{ kHz}$, $f_b = 14.5\text{ kHz}$ with $f_{\text{SAMPLING}} = 400\text{ kHz}$
ANALOG OUTPUT						
Output Voltage Ranges						
Unipolar	0 to +1.25/2.5				Volts	$V_{DD} = +5\text{ V}$, $V_{SS} = 0\text{ V}$
Bipolar	$\pm 1.25/\pm 2.5$				Volts	$V_{DD} = +5\text{ V}$, $V_{SS} = -5\text{ V}$
LOGIC INPUTS						
$\overline{\text{CS}}$, $\overline{\text{X/B}}$, $\overline{\text{WR}}$, $\overline{\text{RANGE}}$, $\overline{\text{RESET}}$, DB0–DB7						
Input Low Voltage, V_{INL}	0.8	0.8	0.8	0.8	V max	
Input High Voltage, V_{INH}	2.4	2.4	2.4	2.4	V min	
Input Leakage Current	10	10	10	10	μA max	$V_{\text{IN}} = 0$ to V_{DD}
Input Capacitance ⁷	10	10	10	10	pF max	
DB0–DB7						
Input Coding (Single Supply)			Binary			
Input Coding (Dual Supply)			2s Complement			
AC CHARACTERISTICS⁷						
Voltage Output Settling Time						Settling time to within $\pm 1/2$ LSB of final value
Positive Full-Scale Change	2	2	2	2	μs max	Typically 1 μs
Negative Full-Scale Change (Single Supply)	4	4	4	4	μs max	Typically 2 μs
Negative Full-Scale Change (Dual Supply)	2	2	2	2	μs max	Typically 1 μs
Digital-to-Analog Glitch Impulse ⁵	15	15	15	15	nV secs typ	
Digital Feedthrough ⁵	1	1	1	1	nV secs typ	
V_{IN} to V_{OUT} Isolation	60	60	60	60	dB typ	$V_{\text{IN}} = \pm 2.5\text{ V}$, 50 kHz Sine Wave
DAC to DAC Crosstalk ⁵ (AD7669 Only)	1				nV secs typ	
DACA to DACB Isolation ⁵ (AD7669 Only)	-70				dB max	
POWER REQUIREMENTS						
V_{DD} Range	4.75/5.25	4.75/5.25	4.75/5.25	4.75/5.25	V min/V max	For Specified Performance
V_{SS} Range (Dual Supplies)	-4.75/-5.25	-4.75/-5.25	-4.75/-5.25	-4.75/-5.25	V min/V max	Specified Performance also applies to $V_{SS} = 0\text{ V}$ for unipolar ranges.
I_{DD} (AD7569)	13	13	13	13	mA max	$V_{\text{OUT}} = V_{\text{IN}} = 2.5\text{ V}$; Logic Inputs = 2.4 V; CLK = 0.8 V
(AD7669)	18				mA max	Output unloaded
I_{SS} (Dual Supplies) (AD7569)	4	4	4	4	mA max	Outputs unloaded
(AD7669)	6				mA max	$V_{\text{OUT}} = V_{\text{IN}} = -2.5\text{ V}$; Logic Inputs = 2.4 V; CLK = 0.8 V
						Output unloaded
						Outputs unloaded
DAC/ADC MATCHING						
Gain Matching ⁶ @ +25°C	1	1	1	1	% typ	V_{IN} to V_{OUT} match with $V_{\text{IN}} = \pm 2.5\text{ V}$, 20 kHz sine wave
T_{MIN} to T_{MAX}	1	1	1	1	% typ	

NOTES

¹Specifications apply to both DACs in the AD7669. V_{OUT} applies to both V_{OUTA} and V_{OUTB} of the AD7669.

²Except where noted, specifications apply for all output ranges including bipolar ranges with dual supply operation.

³Temperature ranges as follows: J, K versions; 0°C to +70°C

A, B versions; -40°C to +85°C

S, T versions; -55°C to +125°C

⁴1 LSB = 4.88 mV for 0 V to +1.25 V output range, 9.76 mV for 0 V to +2.5 V and $\pm 1.25\text{ V}$ ranges and 19.5 mV for $\pm 2.5\text{ V}$ range.

⁵See Terminology.

⁶Includes internal voltage reference error and is calculated after offset error has been adjusted out. Ideal unipolar full-scale voltage is (FS - 1 LSB); ideal bipolar positive full-scale voltage is (FS/2 - 1 LSB) and ideal bipolar negative full-scale voltage is -FS/2.

⁷Sample tested at +25°C to ensure compliance.

Specifications subject to change without notice.

ADC SPECIFICATIONS ($V_{DD} = +5\text{ V} \pm 5\%$; $V_{SS}^1 = \text{RANGE} = \text{AGND}_{\text{DAC}} = \text{AGND}_{\text{DAC}} = \text{DGND} = 0\text{ V}$; $f_{\text{CLK}} = 5\text{ MHz}$ external unless otherwise noted. All specifications T_{MIN} to T_{MAX} unless otherwise noted.) Specifications apply to Mode 1 interface.

Parameter	AD7569 J, A Versions ³ AD7669 J Version	AD7569 K, B Versions	AD7569 S Version	AD7569 T Version	Units	Conditions/Comments
DC ACCURACY						
Resolution ³	8	8	8	8	Bits	
Total Unadjusted Error ⁴	± 3	± 3	± 4	± 4	LSB typ	
Relative Accuracy ⁴	± 1	$\pm 1/2$	± 1	$\pm 1/2$	LSB max	
Differential Nonlinearity ⁴	± 1	$\pm 3/4$	± 1	$\pm 3/4$	LSB max	No Missing Codes
Unipolar Offset Error @ +25°C	± 2	± 1.5	± 2	± 1.5	LSB max	Typical tempco is 10 $\mu\text{V}/^\circ\text{C}$ for +1.25 V range; $V_{SS} = 0\text{ V}$
T_{MIN} to T_{MAX}	± 3	± 2.5	± 3	± 2.5	LSB max	
Bipolar Zero Offset Error @ +25°C	± 3	± 2.5	± 3	± 2.5	LSB max	Typical tempco is 20 $\mu\text{V}/^\circ\text{C}$ for +1.25 V range; $V_{SS} = -5\text{ V}$
T_{MIN} to T_{MAX}	± 3.5	± 3	± 4	± 3.5	LSB max	
Full-Scale Error ⁵ @ +25°C	-4, +0	-4, +0	-4, +0	-4, +0	LSB max	$V_{DD} = 5\text{ V}$
T_{MIN} to T_{MAX}	-5.5, +1.5	-5.5, +1.5	-7.5, +2	-7.5, +2	LSB max	
Δ Full Scale/ ΔV_{DD} , $T_A = +25^\circ\text{C}$	0.5	0.5	0.5	0.5	LSB max	$V_{IN} = +2.5\text{ V}$; $\Delta V_{DD} = \pm 5\%$
Δ Full Scale/ ΔV_{SS} , $T_A = +25^\circ\text{C}$	0.5	0.5	0.5	0.5	LSB max	$V_{IN} = -2.5\text{ V}$; $\Delta V_{SS} = \pm 5\%$
DYNAMIC PERFORMANCE						
Signal-to-Noise Ratio ⁴ (SNR)	44	46	44	45	dB min	$V_{IN} = 100\text{ kHz}$ full-scale sine wave with $f_{\text{SAMPLING}} = 400\text{ kHz}$ ⁶
Total Harmonic Distortion ⁴ (THD)	48	48	48	48	dB max	$V_{IN} = 100\text{ kHz}$ full-scale sine wave with $f_{\text{SAMPLING}} = 400\text{ kHz}$ ⁶
Intermodulation Distortion ⁴ (IMD)	60	60	60	60	dB typ	$f_a = 99\text{ kHz}$, $f_b = 96.7\text{ kHz}$ with $f_{\text{SAMPLING}} = 400\text{ kHz}$
Frequency Response	0.1	0.1	0.1	0.1	dB typ	$V_{IN} = \pm 2.5\text{ V}$, dc to 200 kHz sine wave
Track/Hold Acquisition Time ⁷	200	200	300	300	ns typ	
ANALOG INPUT						
Input Voltage Ranges						
Unipolar		0 to +1.25/ +2.5			Volts	$V_{DD} = +5\text{ V}$; $V_{SS} = 0\text{ V}$
Bipolar		$\pm 1.25/\pm 2.5$			Volts	$V_{DD} = +5\text{ V}$; $V_{SS} = -5\text{ V}$
Input Current	± 300	± 300	± 300	± 300	μA max	See equivalent circuit Figure 5
Input Capacitance	10	10	10	10	pF typ	
LOGIC INPUTS						
CS, RD, ST, CLK, RESET, RANGE						
Input Low Voltage, V_{INL}	0.8	0.8	0.8	0.8	V max	
Input High Voltage, V_{INH}	2.4	2.4	2.4	2.4	V min	
Input Capacitance ⁸	10	10	10	10	pF max	
CS, RD, ST, RANGE, RESET						
Input Leakage Current	10	10	10	10	μA max	$V_{IN} = 0$ to V_{DD}
CLK						
Input Current						
I_{INL}	-1.6	-1.6	-1.6	-1.6	mA max	$V_{IN} = 0\text{ V}$
I_{INH}	40	40	40	40	μA max	$V_{IN} = V_{DD}$
LOGIC OUTPUTS						
DB0-DB7, INT, BUSY						
V_{OL} , Output Low Voltage	0.4	0.4	0.4	0.4	V max	$I_{\text{SINK}} = 1.6\text{ mA}$
V_{OH} , Output High Voltage	4.0	4.0	4.0	4.0	V min	$I_{\text{SOURCE}} = 200\text{ }\mu\text{A}$
DB0-DB7						
Floating State Leakage Current	10	10	10	10	μA max	
Floating State Output Capacitance ⁸	10	10	10	10	pF max	
Output Coding (Single Supply)		Binary				
Output Coding (Dual Supply)		2s Complement				
CONVERSION TIME						
With External Clock	2	2	2	2	μs max	$f_{\text{CLK}} = 5\text{ MHz}$
With Internal Clock, $T_A = +25^\circ\text{C}$	1.6	1.6	1.6	1.6	μs min	Using recommended clock components shown in Figure 21.
	2.6	2.6	2.6	2.6	μs max	Clock frequency can be adjusted by varying R_{CLK} .
POWER REQUIREMENTS						
	As per DAC Specifications					

NOTES

¹Except where noted, specifications apply for all ranges including bipolar ranges with dual supply operation.

²Temperature ranges are as follows: J, K versions; 0°C to +70°C

A, B versions; -40°C to +85°C

S, T versions; -55°C to +125°C

³1 LSB = 4.88 mV for 0 V to +1.25 V range, 9.76 mV for 0 V to +2.5 V and $\pm 1.25\text{ V}$ ranges and 19.5 mV for +2.5 V range.

⁴See Terminology.

⁵Includes internal voltage reference error and is calculated after offset error has been adjusted out. Ideal unipolar last code transition occurs at $(FS - 3/2\text{ LSB})$. Ideal bipolar last code transition occurs at $(FS/2 - 3/2\text{ LSB})$.

⁶Exact frequencies are 101 kHz and 384 kHz to avoid harmonics coinciding with sampling frequency.

⁷Rising edge of BUSY to falling edge of ST. The time given refers to the acquisition time, which gives a 3 dB degradation in SNR from the tested figure.

⁸Sample tested at +25°C to ensure compliance.

Specifications subject to change without notice.

AD7569/AD7669—TIMING CHARACTERISTICS¹ (See Figures 8, 10, 12; $V_{DD} = 5\text{ V} \pm 5\%$; $V_{SS} = 0\text{ V}$ or $-5\text{ V} \pm 5\%$)

Parameter	Limit at 25°C (All Grades)	Limit at T_{MIN}, T_{MAX} (J, K, A, B Grades)	Limit at T_{MIN}, T_{MAX} (S, T Grades)	Units	Test Conditions/Comments
DAC Timing					
t_1	80	80	90	ns min	\overline{WR} Pulse Width
t_2	0	0	0	ns min	$\overline{CS}, \overline{A/B}$ to \overline{WR} Setup Time
t_3	0	0	0	ns min	$\overline{CS}, \overline{A/B}$ to \overline{WR} Hold Time
t_4	60	70	80	ns min	Data Valid to \overline{WR} Setup Time
t_5	10	10	10	ns min	Data Valid to \overline{WR} Hold Time
ADC Timing					
t_6	50	50	50	ns min	\overline{ST} Pulse Width
t_7	110	130	150	ns max	\overline{ST} to \overline{BUSY} Delay
t_8	20	30	30	ns max	\overline{BUSY} to \overline{INT} Delay
t_9	0	0	0	ns min	\overline{BUSY} to \overline{CS} Delay
t_{10}	0	0	0	ns min	\overline{CS} to \overline{RD} Setup Time
t_{11}	60	75	90	ns min	\overline{RD} Pulse Width Determined by t_{13} .
t_{12}	0	0	0	ns min	\overline{CS} to \overline{RD} Hold Time
t_{13}^2	60	75	90	ns max	Data Access Time after \overline{RD} ; $C_L = 20\text{ pF}$
	95	120	135	ns max	Data Access Time after \overline{RD} ; $C_L = 100\text{ pF}$
t_{14}^3	10	10	10	ns min	Bus Relinquish Time after \overline{RD}
	60	75	85	ns max	
t_{15}	65	75	85	ns max	\overline{RD} to \overline{INT} Delay
t_{16}	120	140	160	ns max	\overline{RD} to \overline{BUSY} Delay
t_{17}^2	60	75	90	ns max	Data Valid Time after \overline{BUSY} ; $C_L = 20\text{ pF}$
	90	115	135	ns max	Data Valid Time after \overline{BUSY} ; $C_L = 100\text{ pF}$

NOTES

¹Sample tested at +25°C to ensure compliance. All input control signals are specified with $t_r = t_f = 5\text{ ns}$ (10% to 90% of +5 V) and timed from a voltage level of 1.6 V.

² t_{13} and t_{17} are measured with the load circuits of Figure 1 and defined as the time required for an output to cross either 0.8 V or 2.4 V.

³ t_{14} is defined as the time required for the data line to change 0.5 V when loaded with the circuit of Figure 2.

Specifications subject to change without notice.

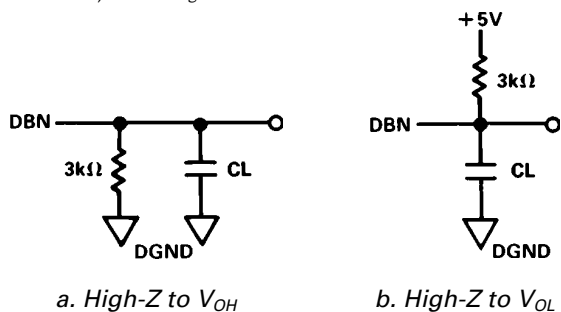


Figure 1. Load Circuits for Data Access Time Test

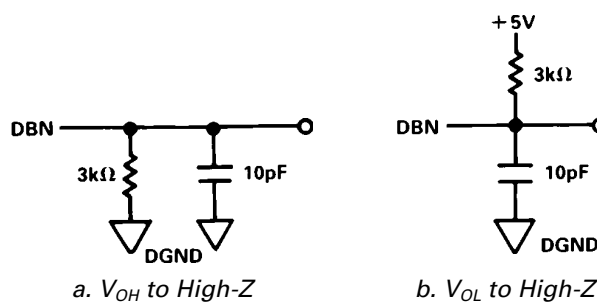


Figure 2. Load Circuits for Bus Relinquish Time Test

ABSOLUTE MAXIMUM RATINGS

V_{DD} to $AGND_{DAC}$ or $AGND_{ADC}$ -0.3 V, +7 V

V_{DD} to $DGND$ -0.3 V, +7 V

V_{DD} to V_{SS} -0.3 V, +14 V

$AGND_{DAC}$ or $AGND_{ADC}$ to $DGND$ -0.3 V, $V_{DD} + 0.3\text{ V}$

$AGND_{DAC}$ to $AGND_{ADC}$ $\pm 5\text{ V}$

Logic Voltage to $DGND$ -0.3 V, $V_{DD} + 0.3\text{ V}$

CLK Input Voltage to $DGND$ -0.3 V, $V_{DD} + 0.3\text{ V}$

V_{OUT} (V_{OUTA} , V_{OUTB}) to

$AGND_{DAC}$ $V_{SS} - 0.3\text{ V}$, $V_{DD} + 0.3\text{ V}$

V_{IN} to $AGND_{ADC}$ $V_{SS} - 0.3\text{ V}$, $V_{DD} + 0.3\text{ V}$

NOTE

¹Output may be shorted to any voltage in the range V_{SS} to V_{DD} provided that the power dissipation of the package is not exceeded. Typical short circuit current for a short to $AGND$ or V_{SS} is 50 mA.

CAUTION

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the AD7569/AD7669 features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.

Power Dissipation (Any Package) to +75°C 450 mW

Derates above 75°C by 6 mW/°C

Operating Temperature Range

Commercial (J, K) 0°C to +70°C

Industrial (A, B) -40°C to +85°C

Extended (S, T) -55°C to +125°C

Storage Temperature Range -65°C to +150°C

Lead Temperature (Soldering, 10 secs) +300°C

*Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other condition above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



NOTE:

The term DAC (Digital-to-Analog Converter) throughout the data sheet applies equally to the dual DACs in the AD7669 as well as to the single DAC of the AD7569 unless otherwise stated. It follows that the term V_{OUT} applies to both V_{OUTA} and V_{OUTB} of the AD7669 also.

TERMINOLOGY**Total Unadjusted Error**

Total unadjusted error is a comprehensive specification that includes internal voltage reference error, relative accuracy, gain and offset errors.

Relative Accuracy (DAC)

Relative Accuracy or endpoint nonlinearity is a measure of the maximum deviation from a straight line passing through the endpoints of the DAC transfer function. It is measured after allowing for offset and gain errors. For the bipolar output ranges, the endpoints of the DAC transfer function are defined as those voltages that correspond to negative full-scale and positive full-scale codes. For the unipolar output ranges, the endpoints are code 1 and code 255. Code 1 is chosen because the amplifier is now working in single supply and, in cases where the true offset of the amplifier is negative, it cannot be seen at code 0. If the relative accuracy were calculated between code 0 and code 255, the “negative offset” would appear as a linearity error. If the offset is negative and less than 1 LSB, it will appear at code 1, and hence the true linearity of the converter is seen between code 1 and code 255.

Relative Accuracy (ADC)

Relative Accuracy is the deviation of the ADC’s actual code transition points from a straight line drawn between the endpoints of the ADC transfer function. For the bipolar input ranges, these points are the measured, negative, full-scale transition point and the measured, positive, full-scale transition point. For the unipolar ranges, the straight line is drawn between the measured first LSB transition point and the measured full-scale transition point.

Differential Nonlinearity

Differential Nonlinearity is the difference between the measured change and an ideal 1 LSB change between any two adjacent codes. A specified differential nonlinearity of ± 1 LSB max ensures monotonicity (DAC) or no missed codes (ADC). A differential nonlinearity of $\pm 3/4$ LSB max ensures that the minimum step size (DAC) or code width (ADC) is $1/4$ LSB, and the maximum step size or code width is $3/4$ LSB.

Digital-to-Analog Glitch Impulse

Digital-to-Analog Glitch Impulse is the impulse injected into the analog output when the digital inputs change state with the DAC selected. It is normally specified as the area of the glitch in nV secs and is measured when the digital input code is changed by 1 LSB at the major carry transition.

Digital Feedthrough

Digital Feedthrough is also a measure of the impulse injected to the analog output from the digital inputs, but is measured when the DAC is not selected. It is essentially feedthrough across the die and package. It is also a measure of the glitch impulse transferred to the analog output when data is read from the internal ADC. It is specified in nV secs and is measured with \overline{WR} high and a digital code change from all 0s to all 1s.

DAC-to-DAC Crosstalk (AD7669 Only)

The glitch energy transferred to the output of one DAC due to an update at the output of the second DAC. The figure given is the worst case and is expressed in nV secs. It is measured with an update voltage of full scale.

DAC-to-DAC Isolation (AD7669 Only)

DAC-to-DAC Isolation is the proportion of a digitized sine wave from the output of one DAC, which appears at the output of the second DAC (loaded with all 1s). The figure given is the worst case for the second DAC output and is expressed as a ratio in dBs. It is measured with a digitized sine wave ($f_{\text{SAMPLING}} = 100$ kHz) of 20 kHz at 2.5 V pk-pk.

Signal-to-Noise Ratio

Signal-to-Noise Ratio (SNR) is the measured signal to noise at the output of the converter. The signal is the rms magnitude of the fundamental. Noise is the rms sum of all the nonfundamental signals (excluding dc) up to half the sampling frequency. SNR is dependent on the number of quantization levels used in the digitization process; the more levels, the smaller the quantization noise. The theoretical SNR for a sine wave is given by

$$SNR = (6.02N + 1.76) \text{ dB}$$

where N is the number of bits. Thus for an ideal 8-bit converter, $SNR = 50$ dB.

Harmonic Distortion

Harmonic Distortion is the ratio of the rms sum of harmonics to the fundamental. For the AD7569/AD7669, Total Harmonic Distortion (THD) is defined as

$$20 \log \sqrt{\frac{V_2^2 + V_3^2 + V_4^2 + V_5^2 + V_6^2}{V_1^2}}$$

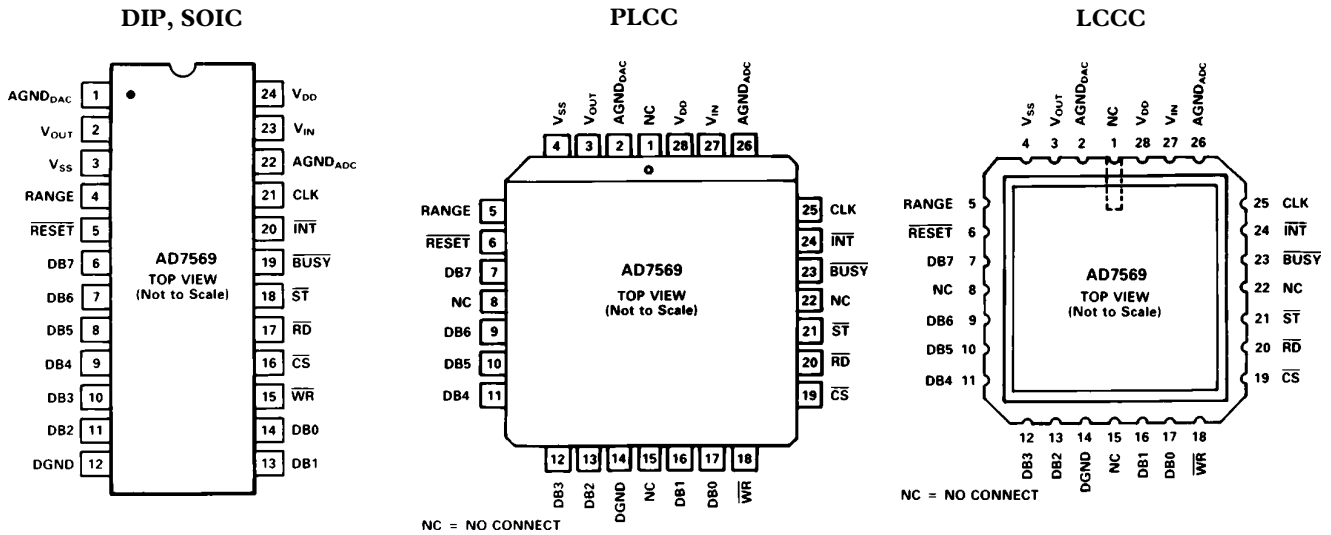
where V_1 is the rms amplitude of the fundamental and V_2 , V_3 , V_4 , V_5 and V_6 are the rms amplitudes of the individual harmonics.

Intermodulation Distortion

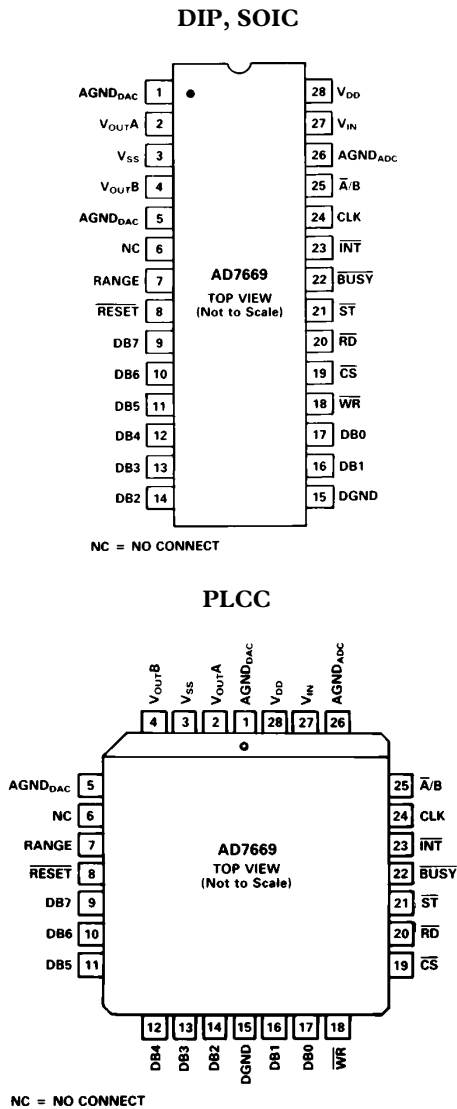
With inputs consisting of sine waves at two frequencies, f_a and f_b , any active device with nonlinearities will create distortion products, of order $(m + n)$, at sum and difference frequencies of $m f_a \pm n f_b$ where $m, n = 0, 1, 2, 3, \dots$. Intermodulation terms are those for which m or n is not equal to zero. For example, the second order terms include $(f_a + f_b)$ and $(f_a - f_b)$ and the third order terms include $(2f_a + f_b)$, $(2f_a - f_b)$, $(f_a + 2f_b)$ and $(f_a - 2f_b)$.

AD7569/AD7669

AD7569 PIN CONFIGURATIONS



AD7669 PIN CONFIGURATIONS



ORDERING GUIDE

Model	Temperature Range	Relative Accuracy T _{MIN} -T _{MAX}	Package Option ¹
AD7569JN	0°C to +70°C	±1 LSB	N-24
AD7569JR	0°C to +70°C	±1 LSB	R-24
AD7569AQ	-40°C to +85°C	±1 LSB	Q-24
AD7569SQ ²	-55°C to +125°C	±1 LSB	Q-24
AD7569BN	-40°C to +85°C	±0.5 LSB	N-24
AD7569KN	0°C to +70°C	±0.5 LSB	N-24
AD7569BR	-40°C to +85°C	±0.5 LSB	R-24
AD7569BQ	-40°C to +85°C	±0.5 LSB	Q-24
AD7569TQ ²	-55°C to +125°C	±1/2 LSB	Q-24
AD7569JP	0°C to +70°C	±1 LSB	P-28A
AD7569SE ²	-55°C to +125°C	±1 LSB	E-28A
AD7569KP	0°C to +70°C	±1/2 LSB	P-28A
AD7569TE ²	-55°C to +125°C	±1/2 LSB	E-28A
AD7669AN	-40°C to +85°C	±1 LSB	N-28
AD7669JN	0°C to +70°C	±1 LSB	N-28
AD7669JP	0°C to +70°C	±1 LSB	P-28A
AD7669AR	-40°C to +85°C	±1 LSB	R-28
AD7669JR	0°C to +70°C	±1 LSB	R-28

NOTES

¹E = Leadless Ceramic Chip Carrier; N = Plastic DIP; P = Plastic Leaded Chip Carrier; Q = Cerdip; R = Small Outline SOIC.

²To order MIL-STD-883, Class B processed parts, add /883B to part number. Contact your local sales office for military data sheet.

PIN FUNCTION DESCRIPTION

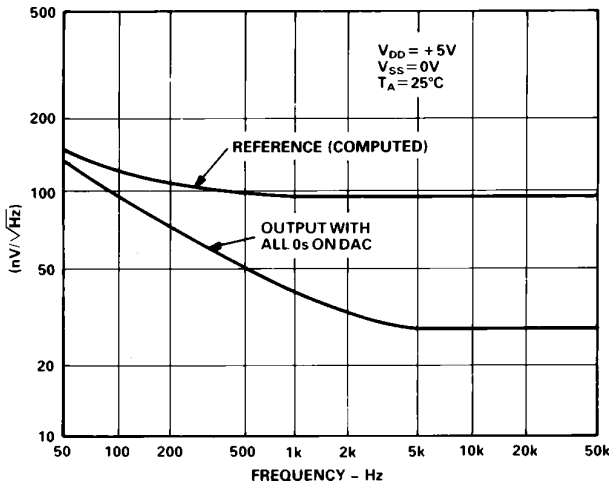
(Applies to the AD7569 and AD7669 unless otherwise stated.)

Pin Mnemonic	Description	Pin Mnemonic	Description
AGND _{DAC}	Analog Ground for the DAC(s). Separate ground return paths are provided for the DAC(s) and ADC to minimize crosstalk.	\overline{CS}	Chip Select Input (Active Low). The device is selected when this input is active.
V _{OUT} (V _{OUTA} , V _{OUTB})	Output Voltage. V _{OUT} is the buffered output voltage from the AD7569 DAC. V _{OUTA} and V _{OUTB} are the buffered DAC output voltages from the AD7669. Four different output voltage ranges can be achieved (see Table I).	\overline{RD}	READ Input (Active Low). This input must be active to access data from the part. In the Mode 2 interface, \overline{RD} going low starts conversion. It is used in conjunction with the \overline{CS} input (see Digital Interface Section).
V _{SS}	Negative Supply Voltage (−5 V for dual supply or 0 V for single supply). This pin is also used with the RANGE pin to select the different input/output ranges and changes the data format from binary (V _{SS} = 0 V) to 2s complement (V _{SS} = −5 V) (see Table I).	\overline{ST}	Start Conversion (Edge triggered). This is used when precise sampling is required. The falling edge of \overline{ST} starts conversion and drives \overline{BUSY} low. The \overline{ST} signal is not gated with CS.
RANGE	Range Selection Input. This is used with the V _{SS} input to select the different ranges as per Table I. The range selected applies to both the analog input voltage of the ADC and the output voltage from the DAC(s).	\overline{BUSY}	BUSY Status Output (Active Low). When this pin is active, the ADC is performing a conversion. The input signal is held prior to the falling edge of \overline{BUSY} (see Digital Interface Section).
\overline{RESET}	Reset Input (Active Low). This is an asynchronous system reset that clears the DAC register(s) to all 0s and clears the \overline{INT} line of the ADC (i.e., makes the ADC ready for new conversion). In unipolar operation, this input sets the output voltage to 0 V; in bipolar operation, it sets the output to negative full scale.	\overline{INT}	INTERRUPT Output (Active Low). \overline{INT} going low indicates that the conversion is complete. \overline{INT} goes high on the rising edge of \overline{CS} or \overline{RD} and is also set high by a low pulse on \overline{RESET} (see Digital Interface Section).
DB7	Data Bit 7. Most Significant Bit (MSB).	$\overline{A/B}$ (AD7669 Only)	DAC Select Input. This input selects which DAC register data is written to under control of \overline{CS} and \overline{WR} . With this input low, data is written to the DACA register; with this input high, data is written to the DACB register.
DB6–DB2	Data Bit 6 to Data Bit 2.	CLK	A TTL compatible clock signal may be used to determine the ADC conversion time. Internal clock operation is achieved by connecting a resistor and capacitor to ground.
DGND	Digital Ground.	AGND _{ADC}	Analog Ground for the ADC.
DB1	Data Bit 1.	V _{IN}	Analog Input. Various input ranges can be selected (see Table I).
DB0	Data Bit 0. Least Significant Bit (LSB).	V _{DD}	Positive Supply Voltage (+5 V).
\overline{WR}	Write Input (Edge triggered). This is used in conjunction with \overline{CS} to write data into the AD7569 DAC register. It is used in conjunction with \overline{CS} and $\overline{A/B}$ to write data into the selected DAC register of the AD7669. Data is transferred on the rising edge of \overline{WR} .		

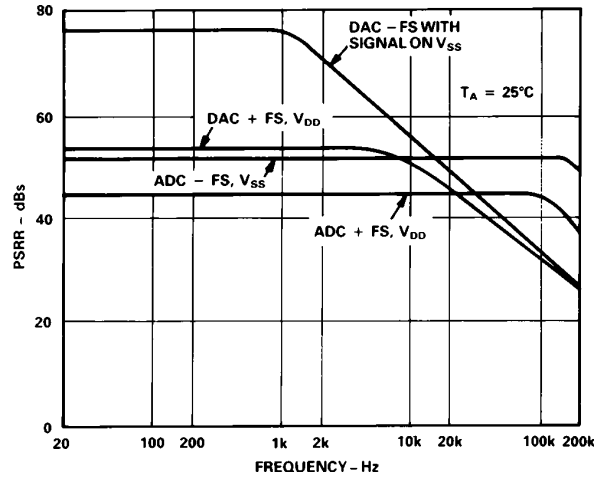
Table I. Input/Output Ranges

Range	V _{SS}	Input/Output Voltage Range	DB0–DB7 Data Format
0	0 V	0 V to +1.25 V	Binary
1	0 V	0 V to +2.5 V	Binary
0	−5 V	±1.25 V	2s Complement
1	−5 V	±2.5 V	2s Complement

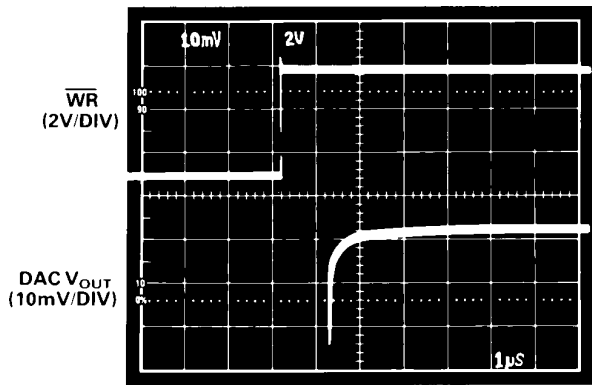
AD7569/AD7669—Typical Performance Graphs



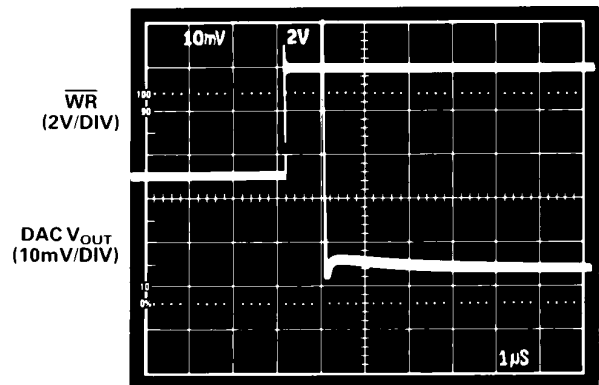
Noise Spectral Density vs. Frequency



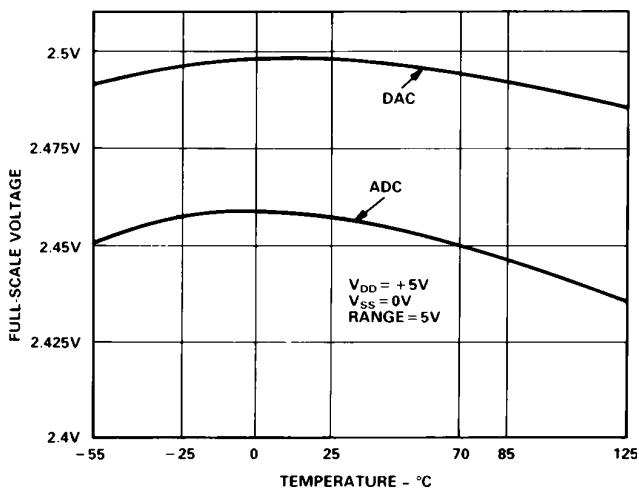
Power Supply Rejection Ratio vs. Frequency



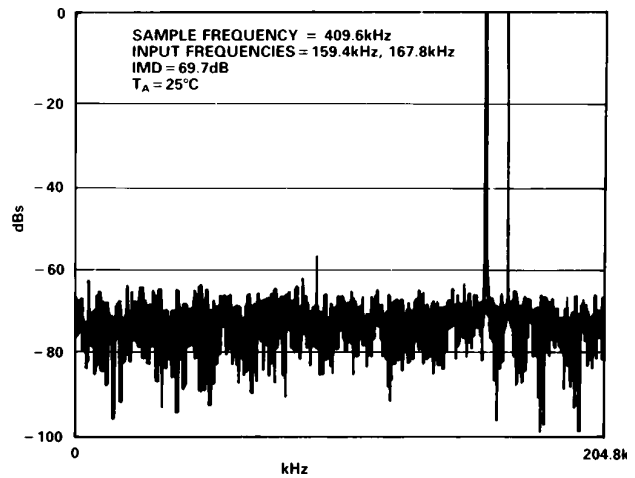
Positive-Going Settling Time (± 2.5 V Range)



Negative-Going Settling Time (± 2.5 V Range)



DAC/ADC Full-Scale Temperature Coefficient



IMD Plot for ADC

CIRCUIT DESCRIPTION

D/A SECTION

The AD7569 contains an 8-bit, voltage-mode, D/A converter that uses eight equally weighted current sources switched into an R-2R ladder network to give a direct but unbuffered 0 V to +1.25 V output range. The AD7669 is similar, but contains two D/A converters. The current sources are fabricated using PNP transistors. These transistors allow current sources that are driven from positive voltage logic and give a zero-based output range. The output voltage from the voltage switching R-2R ladder network has the same positive polarity as the reference; therefore, the D/A converter can be operated from a single power supply rail.

The PNP current sources are generated using the on-chip bandgap reference and a control amplifier. The current sources are switched to either the ladder or $AGND_{DAC}$ by high speed p-channel switches. These high-speed switches ensure a fast settling time for the output voltage of the DAC. The R-2R ladder network of the DAC consists of highly stable, thin-film resistors. A simplified circuit diagram for the D/A converter section is shown in Figure 3. An identical D/A converter is used as part of the A/D converter, which is discussed later.

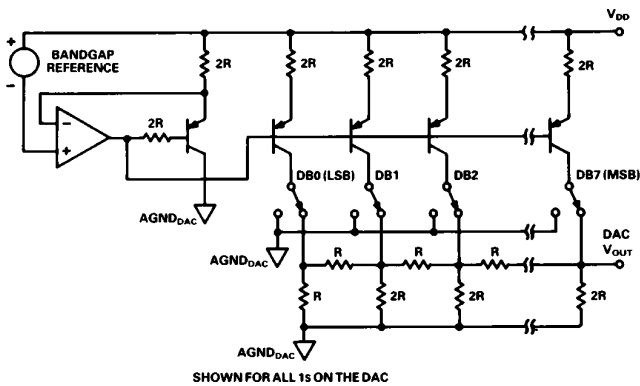


Figure 3. DAC Simplified Circuit Diagram

OP AMP SECTION

The output from the D/A converter is buffered by a high speed, noninverting op amp. This op amp is capable of developing ± 2.5 V across a 2 k Ω and 100 pF load to $AGND_{DAC}$. The amplifier can be operated from a single +5 V supply to give two unipolar output ranges, or from dual supplies (± 5 V) to allow two bipolar output ranges.

The feedback path of the amplifier contains a gain/offset network that provides four voltage ranges at the output of the op amp. The output voltage range is determined by the RANGE and V_{SS} inputs. (See Table I in the Pin Function Description section.) The four possible output ranges are: 0 V to +1.25 V, 0 V to +2.5 V, ± 1.25 V and ± 2.5 V. It should be noted that whichever range is selected for the output amplifier also applies to the input voltage range of the A/D converter.

The output amplifier settles to within 1/2 LSB of its final value in typically less than 500 ns. Operating the part from single or dual supplies has no effect on the positive-going settling time. However, the negative-going output settling time to voltages near 0 V in single supply will be slightly longer than the settling time to negative full scale for dual supply operation. Additionally, to ensure that the output voltage can go to 0 V in single

supply, a transistor on the output acts as a passive pull-down with output voltages near 0 V with $V_{SS} = 0$ V. This means that the sink capability of the amplifier is reduced as the output voltage nears 0 V in single supply. In dual supply operation the full sink capability of 1.25 mA is maintained over the entire output voltage range.

For all other parameters, the single and dual supply performances of the amplifier are essentially identical. The output noise from the amplifier, with full scale on the DAC, is 200 μ V peak-to-peak. The spot noise at 1 kHz is 35 nV/\sqrt{Hz} with all 0s on the DAC. A noise spectral density versus frequency plot for the amplifier is shown in the typical performance graphs.

VOLTAGE REFERENCE

The AD7569/AD7669 contains an on-chip bandgap reference that provides a low noise, temperature compensated reference voltage for both the DAC and the ADC. The reference is trimmed for absolute accuracy and temperature coefficient. The bandgap reference is generated with respect to V_{DD} . It is buffered by a separate control amplifier for both the DAC and the ADC reference. This can be seen in the DAC ladder network configuration in Figure 3.

DIGITAL SECTION

The data pins on the AD7569/AD7669 provide a connection between the external bus and DAC data inputs and ADC data outputs. The threshold levels of all digital inputs and outputs are compatible with either TTL or 5 V CMOS levels. Internal input protection of all digital pins is achieved by on-chip distributed diodes.

The data format is straight binary when the part is used in single supply ($V_{SS} = 0$ V). However, when a V_{SS} of -5 V is applied, the data format becomes twos complement. This data format applies to the digital inputs of the DAC and the digital outputs of the ADC.

ADC SECTION

The analog-to-digital converter on the AD7569/AD7669 uses the successive approximation technique to achieve a fast conversion time of 2 μ s and provides an 8-bit parallel digital output. The reference for the ADC is provided by the on-chip bandgap reference.

Conversion start is controlled by \overline{ST} or by \overline{CS} and \overline{RD} . Once a conversion has been started, another conversion start should not be attempted until the conversion in progress is completed. Exercising the \overline{RESET} input does not affect conversion; the \overline{RESET} input resets the \overline{INT} line high, which is useful in interrupt driven systems where a READ has not been performed at the end of the previous conversion. The \overline{INT} line does not have to be cleared at the end of conversion. The ADC will continue to convert correctly, but the function of the \overline{INT} line will be affected.

Figure 4 shows the operating waveforms for a conversion cycle. The analog input voltage, V_{IN} , is held 50 ns typical after the falling edge of \overline{ST} or $(\overline{CS} \& \overline{RD})$. The MSB decision is made approximately 50 ns after the second falling edge of the input CLK following a conversion start. If t_1 in Figure 4 is greater than 50 ns, then the falling edge of the input CLK will be seen as the first falling clock edge. If t_1 is less than 50 ns, the first falling clock edge of the conversion will not occur until one clock cycle later. The succeeding bit decisions are made approximately 50 ns after a CLK edge until conversion is complete.

AD7569/AD7669

At the end of conversion, the SAR contents are transferred to the output latch, and the SAR is reset in readiness for a new conversion. A single conversion lasts for 8 input clock cycles.

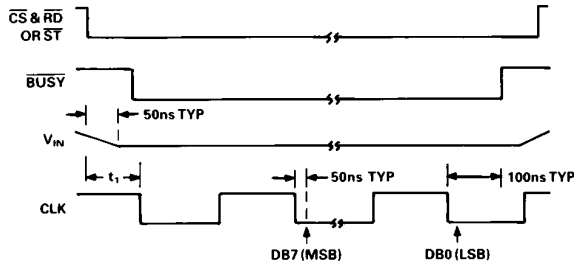


Figure 4. Operating Waveforms Using External Clock

ANALOG INPUT

The analog input of the AD7569/AD7669 feeds into an on-chip track-and-hold amplifier. To accommodate different full-scale ranges, the analog input signal is conditioned by a gain/offset network that conditions all input ranges so the internal ADC always works with a 0 V to +1.25 V signal. As a result, the input current on the V_{IN} input varies with the input range selected as shown in Figure 5.

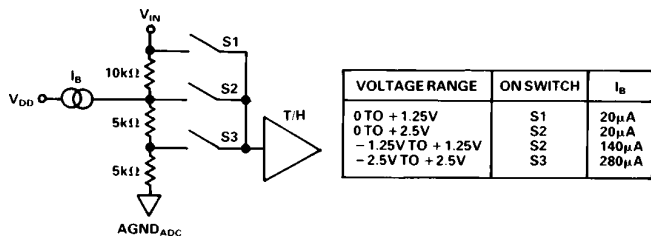


Figure 5. Equivalent V_{IN} Circuit

TRACK-AND-HOLD

The track-and-hold (T/H) amplifier on the analog input of the AD7569/AD7669 allows the ADC to accurately convert an input sine wave of 2.5 V peak-to-peak amplitude up to a frequency of 200 kHz, the Nyquist frequency of the ADC when operated at its maximum throughput rate of 400 kHz. This maximum rate of conversion includes conversion time and time between conversions. Because the input bandwidth of the T/H amplifier is much larger than 200 kHz, the input signal should be band-limited to avoid converting high-frequency noise components.

The operation of this T/H amplifier is essentially transparent to the user. The T/H amplifier goes from its tracking mode to its hold mode at the start of conversion. This occurs when the ADC receives a conversion start command from either \overline{ST} or \overline{CS} & \overline{RD} . At the end of conversion (\overline{BUSY} going high), the T/H reverts back to tracking the input signal.

EXTERNAL CLOCK

The AD7569/AD7669 ADC can be used with its on-chip clock or with an externally applied clock. When using an external clock, the CLK input of the AD7569/AD7669 may be driven directly from 74HC, 4000B series buffers (such as 4049) or from TTL buffers. When conversion is complete, the internal clock is disabled. The external clock can continue to run between conversions without being disabled. The mark/space ratio of the external clock can vary from 70/30 to 30/70.

INTERNAL CLOCK

Clock pulses are generated by the action of an internal current source charging the external capacitor (C_{CLK}) and this external capacitor discharging through the external resistor (R_{CLK}). When a conversion is complete, this internal clock stops operating and the CLK pin goes to the DGND potential. Connections for R_{CLK} and C_{CLK} are shown in the operating diagram of Figure 21. The nominal conversion time versus temperature for the recommended R_{CLK} and C_{CLK} combination is shown in Figure 6. The internal clock provides a convenient clock source for the AD7569/AD7669. Due to process variations, the actual operating frequency for this R_{CLK}/C_{CLK} combination can vary from device to device by up to $\pm 25\%$.

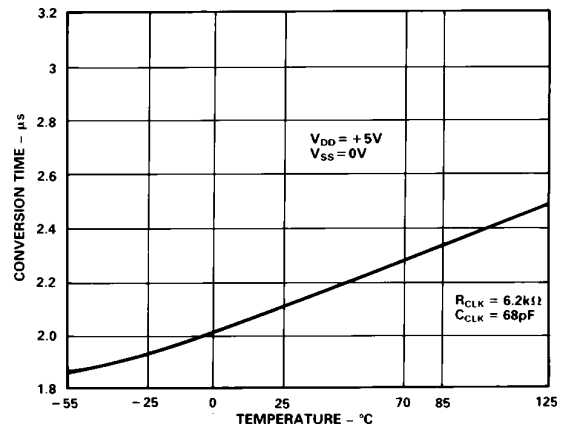


Figure 6. Conversion Time vs. Temperature for Internal Clock Operation

DIGITAL INTERFACE

DAC Timing and Control—AD7569

Table II shows the truth table for DAC operation for the AD7569. The part contains an 8-bit DAC register, which is loaded from the data bus under control of \overline{CS} and \overline{WR} . The data contained in the DAC register determines the analog output from the DAC. The \overline{WR} input is an edge-triggered input, and data is transferred into the DAC register on the rising edge of \overline{WR} . Holding \overline{CS} and \overline{WR} low does not make the DAC register transparent.

Table II. AD7569 DAC Truth Table

\overline{CS}	\overline{WR}	\overline{RESET}	DAC Function
H	H	H	DAC Register Unaffected
L	L	H	DAC Register Unaffected
L	\bar{f}	H	DAC Register Updated
\bar{f}	L	H	DAC Register Updated
X	X	L	DAC Register Loaded with All Zeros

L = Low State, H = High State, X = Don't Care

The contents of the DAC register are reset to all 0s by an active low pulse on the \overline{RESET} line, and for the unipolar output ranges, the output remains at 0 V after \overline{RESET} returns high. For the bipolar output ranges, a low pulse on \overline{RESET} causes the output to go to negative full scale. In unipolar applications, the \overline{RESET} line can be used to ensure power-up to 0 V on the AD7569 DAC output and is also useful when used as a zero override in system calibration cycles. If the \overline{RESET} input is connected to the system

$\overline{\text{RESET}}$ line, the DAC output resets to 0 V when the entire system is reset. Figure 7 shows the input control logic for the AD7569 DAC; the write cycle timing diagram is shown in Figure 8.

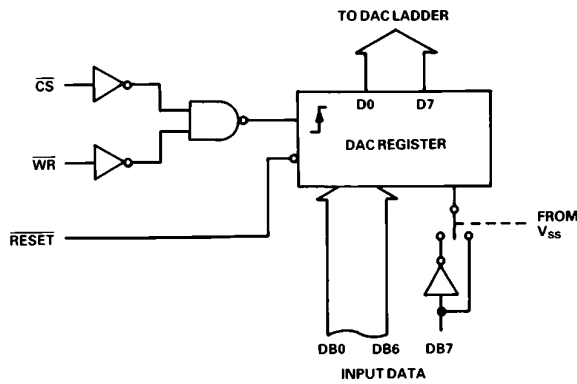
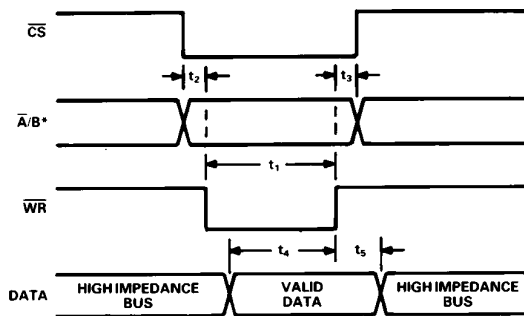


Figure 7. AD7569 DAC Input Control Logic



*AD7669 ONLY

NOTES

1. ALL INPUT RISE AND FALL TIMES MEASURED FROM 10% TO 90% OF +5V.

$t_R = t_F = 5\text{ns}$

2. TIMING MEASUREMENT REFERENCE LEVEL IS

$$\frac{V_{IH} + V_{IL}}{2}$$

Figure 8. AD7569/AD7669 Write Cycle Timing Diagram

DAC Timing and Control—AD7669

Table III shows the truth table for the dual DAC operation of the AD7669. The part contains two 8-bit DAC registers that are loaded from the data bus under the control of $\overline{\text{CS}}$, $\overline{\text{A/B}}$ and $\overline{\text{WR}}$. Address line $\overline{\text{A/B}}$ selects which DAC register the data is loaded to. The data contained in the DAC registers determines the analog output from the respective DACs. The $\overline{\text{WR}}$ input is an edge-triggered input, and data is transferred into the selected DAC register on the rising edge of $\overline{\text{WR}}$. Holding $\overline{\text{CS}}$ and $\overline{\text{WR}}$ low does not make the selected DAC register transparent. The $\overline{\text{A/B}}$ input should not be changed while $\overline{\text{CS}}$ and $\overline{\text{WR}}$ are low.

Table III. AD7669 DAC Truth Table

$\overline{\text{CS}}$	$\overline{\text{WR}}$	$\overline{\text{A/B}}$	$\overline{\text{RESET}}$	DAC Function
H	H	X	H	DAC Registers Unaffected
L	\bar{f}	L	H	DACA Register Updated
\bar{f}	L	L	H	DACA Register Updated
L	\bar{f}	H	H	DACB Register Updated
\bar{f}	L	H	H	DACB Register Updated
X	X	X	L	DAC Registers Loaded with All Zeros

L = Low State, H = High State, X = Don't Care

The contents of the DAC registers are reset to all 0s by an active low pulse on the $\overline{\text{RESET}}$ line, and for the unipolar output ranges, the outputs remain at 0 V after $\overline{\text{RESET}}$ returns high. For the bipolar output ranges, a low pulse on $\overline{\text{RESET}}$ causes the outputs to go to negative full scale. In unipolar applications, the $\overline{\text{RESET}}$ line can be used to ensure power-up to 0 V on the AD7669 DAC outputs and is also useful when used as a zero override in system calibration cycles. If the $\overline{\text{RESET}}$ input is connected to the system $\overline{\text{RESET}}$ line, then the DAC outputs reset to 0 V when the entire system is reset. Figure 9 shows the DAC input control logic for the AD7669, and the write cycle timing diagram is shown in Figure 8.

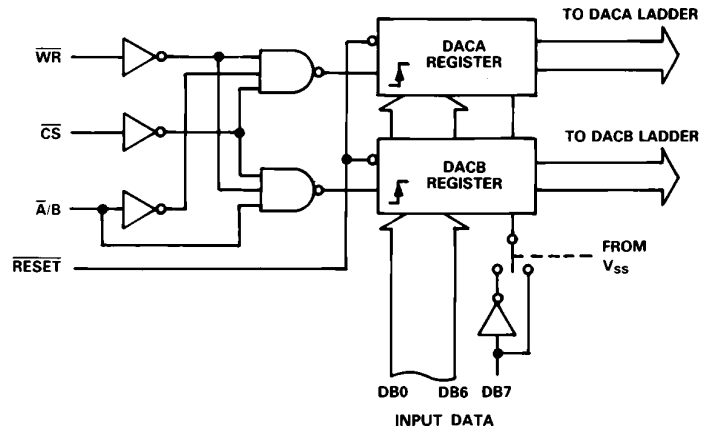


Figure 9. AD7669 DAC Control Logic

ADC Timing and Control

The ADC on the AD7569/AD7669 is capable of two basic operating modes. In the first mode, the $\overline{\text{ST}}$ line is used to start conversion and drive the track-and-hold into hold mode. At the end of conversion, the track-and-hold returns to its tracking mode. The second mode is achieved by hard-wiring the $\overline{\text{ST}}$ line high. In this case, $\overline{\text{CS}}$ and $\overline{\text{RD}}$ start conversion, and the microprocessor is driven into a WAIT state for the duration of conversion by $\overline{\text{BUSY}}$.

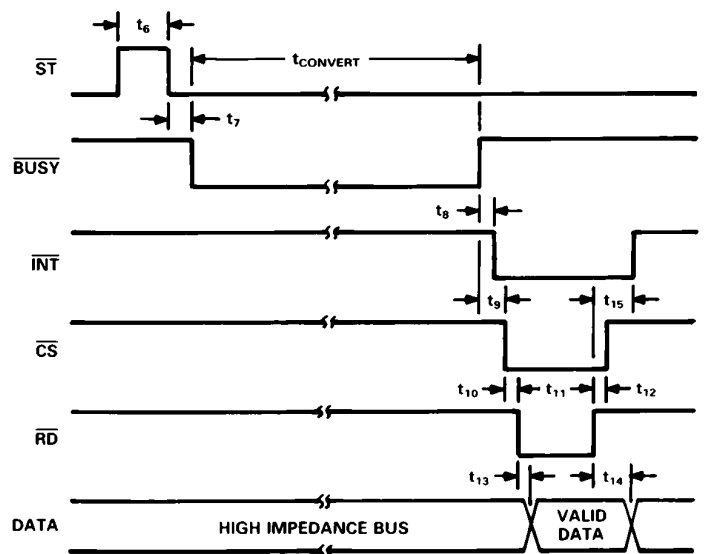


Figure 10. ADC Mode 1 Interface Timing

AD7569/AD7669

MODE 1 INTERFACE

The timing diagram for the first mode is shown in Figure 10. It can be used in digital signal processing and other applications where precise sampling in time is required. In these applications, it is important that the signal sampling occurs at exactly equal intervals to minimize errors due to sampling uncertainty or jitter. In these cases, the \overline{ST} line is driven by a timer or some precise clock source.

The falling edge of the \overline{ST} pulse starts conversion and drives the AD7569/AD7669 track-and-hold amplifier into its hold mode. $BUSY$ stays low for the duration of conversion and returns high at the end of conversion and the track-and hold amplifier reverts to its tracking mode on this rising edge of $BUSY$. The \overline{INT} line can be used to interrupt the microprocessor. A READ to the AD7569/AD7669 address accesses the data, and the \overline{INT} line is reset on the rising edge of \overline{CS} or \overline{RD} . Alternatively, the \overline{INT} can be used to trigger a pulse that drives the \overline{CS} and \overline{RD} and places the data into a FIFO or buffer memory. The microprocessor can then read a batch of data from the FIFO or buffer memory at some convenient time. The \overline{ST} input should not be high when \overline{RD} is brought low; otherwise, the part will not operate correctly in this mode.

It is important, especially in systems where the conversion start (\overline{ST} pulse) is asynchronous to the microprocessor, that a READ does not occur during a conversion. Trying to read data from the device during a conversion can cause errors to the conversion in progress. Also, pulsing the \overline{ST} line a second time before conversion ends should be avoided since it too can cause errors in the conversion result. In applications where precise sampling is not critical, the \overline{ST} pulse can be generated from a microprocessor \overline{WR} or \overline{RD} line gated with a decoded address (different from AD7569/AD7669 \overline{CS} address).

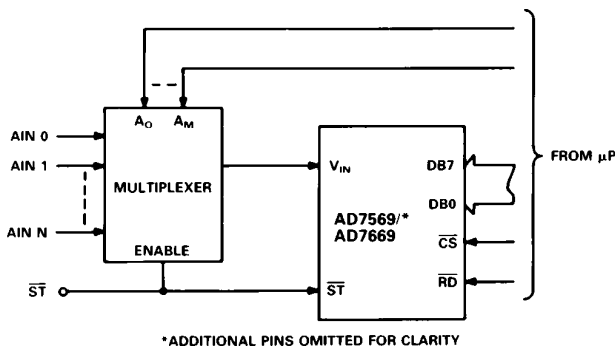


Figure 11. Multichannel Inputs

This interface mode is also useful in applications where a number of input channels are required to be converted by the ADC. Figure 11 shows the circuit configuration for such an application. The signal that drives the \overline{ST} input of the AD7569/AD7669 is also used to drive the ENABLE input of the multiplexer. The multiplexer is enabled on the rising edge of the \overline{ST} pulse while the input signal is held on the falling edge; therefore, the signal must have settled to within 8 bits over the duration of this \overline{ST} pulse. The settling time, including t_{ON} (ENABLE) of the multiplexer plus the T/H acquisition time (typically 200 ns), thus determines the width of the \overline{ST} pulse. This is suited to applications where a number of input channels needs to be successively sampled or scanned.

MODE 2 INTERFACE

The second interface mode is intended for use with microprocessors, which can be forced into a WAIT state for at least 2 μ s. The \overline{ST} line of the AD7569/AD7669 must be hardwired high to achieve this mode. The microprocessor starts a conversion and is halted until the result of the conversion is read from the converter. Conversion is initiated by executing a memory READ to the AD7569/AD7669 address, bringing \overline{CS} and \overline{RD} low. $BUSY$ subsequently goes low (forcing the microprocessor READY or WAIT input low), placing the microprocessor into a WAIT state. The input signal is held on the falling edge of \overline{RD} (assuming \overline{CS} is already low or is coincident with \overline{RD}). When the conversion is complete ($BUSY$ goes high), the processor completes the memory READ and acquires the newly converted data. While conversion is in progress, the ADC places old data (from the previous conversion) on the data bus. The timing diagram for this interface is shown in Figure 12.

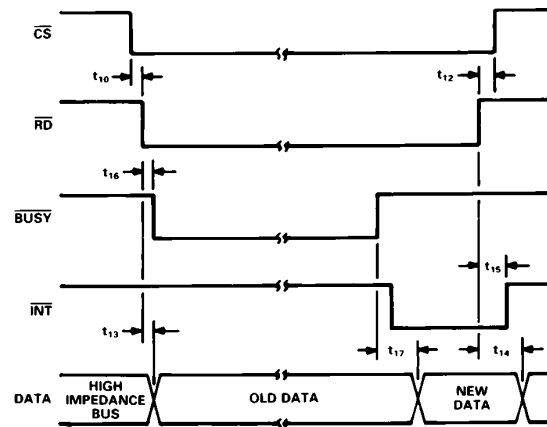


Figure 12. ADC Mode 2 Interface Timing

The major advantage of this interface is that it allows the microprocessor to start conversion, WAIT, and then READ data with a single READ instruction. The user does not have to worry about servicing interrupts or ensuring that software delays are long enough to avoid reading during conversion. The fast conversion time of the ADC ensures that for many microprocessors, the processor is not placed in a WAIT state for an excessive amount of time.

DIGITAL SIGNAL PROCESSING APPLICATIONS

In Digital Signal Processing (DSP) application areas such as voice recognition, echo cancellation and adaptive filtering, the dynamic characteristics (SNR, Harmonic Distortion, Intermodulation Distortion) of both the ADC and DAC are critical. The AD7569/AD7669 is specified dynamically as well as with standard dc specifications. Because the track/hold amplifier has a wide bandwidth, an antialiasing filter should be placed on the V_{IN} input to avoid aliasing of high-frequency noise back into the band of interest.

The dynamic performance of the ADC is evaluated by applying a sine-wave signal of very low distortion to the V_{IN} input, which is sampled at a 409.6 kHz sampling rate. A Fast Fourier Transform (FFT) plot or Histogram plot is then generated from which SNR, harmonic distortion and dynamic differential nonlinearity data can be obtained. For the DAC, the codes for an ideal sine wave are stored in PROM and loaded down to the DAC. The output spectrum is analyzed, using a spectrum analyzer to evaluate SNR

and harmonic distortion performance. Similarly, for intermodulation distortion, an input (either to V_{IN} or DAC code) consisting of pure sine waves at two frequencies is applied to the AD7569/AD7669.

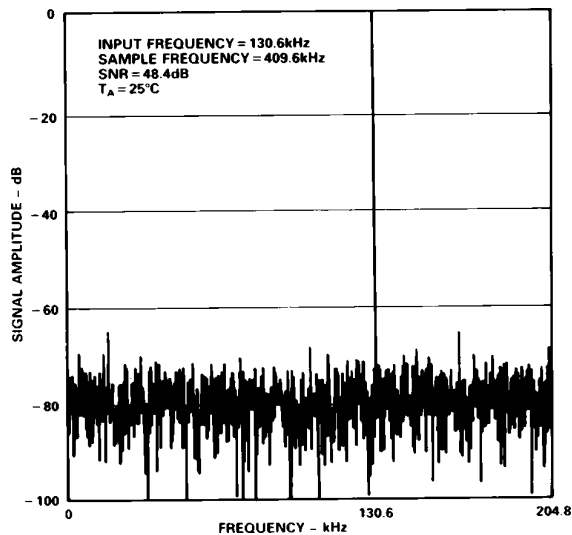


Figure 13. ADC FFT Plot

Figure 13 shows a 2048 point FFT plot of the ADC with an input signal of 130 kHz. The SNR is 48.4 dB. It can be seen that most of the harmonics are buried in the noise floor. It should be noted that the harmonics are taken into account when calculating the SNR. The relationship between SNR and resolution (N) is expressed by the following equation:

$$SNR = (6.02N + 1.76) \text{ dB}$$

This is for an ideal part with no differential or integral linearity errors. These errors will cause a degradation in SNR. By working backward from the above equation, it is possible to get a measure of ADC performance expressed in effective number of bits (N). This effective number of bits is plotted versus frequency in Figure 14. The effective number of bits typically falls between 7.7 and 7.8, corresponding to SNR figures of 48.1 dB and 48.7 dB.

Figure 15 shows a spectrum analyzer plot of the output spectrum from the DAC with an ideal sine-wave table loaded to the data inputs of the DAC. In this case, the SNR is 46 dB.

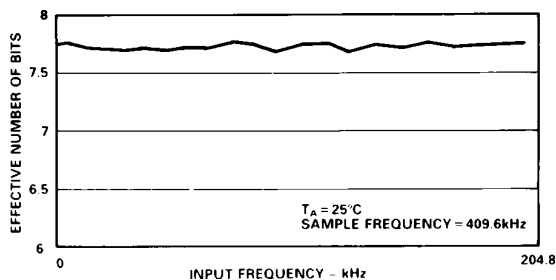


Figure 14. Effective Number of Bits vs. Frequency

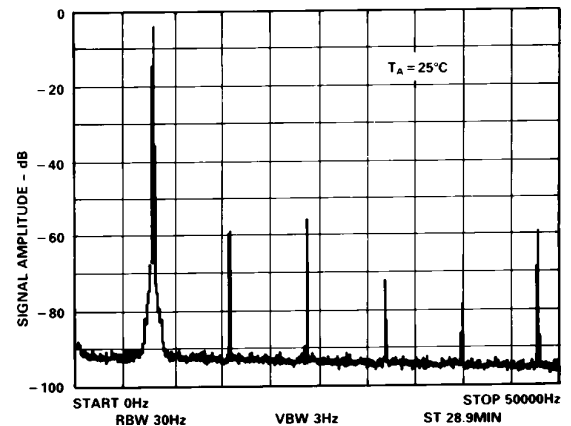


Figure 15. DAC Output Spectrum

HISTOGRAM PLOT

When a sine wave of specified frequency is applied to the V_{IN} input of the AD7569/AD7669 and several thousand samples are taken, it is possible to plot a histogram showing the frequency of occurrence of each of the 256 ADC codes. If a particular step is wider than the ideal 1 LSB width, the code associated with that step will accumulate more counts than for the code for an ideal step. Likewise, a step narrower than ideal width will have fewer counts. Missing codes are easily seen because a missing code means zero counts for a particular code. The absence of large spikes in the plot indicates small differential nonlinearity.

Figure 16 shows a histogram plot for the ADC indicating very small differential nonlinearity and no missing codes for an input frequency of 204 kHz. For a sine-wave input, a perfect ADC would produce a cusp probability density function described by the equation

$$p(V) = \frac{1}{\pi(A^2 - V^2)^{1/2}}$$

where A is the peak amplitude of the sine wave and $p(V)$ the probability of occurrence at a voltage V .

The histogram plot of Figure 16 corresponds very well with this cusp shape.

Further typical plots of the performance of the AD7569/AD7669 are shown in the Typical Performance Graphs section of the data sheet.

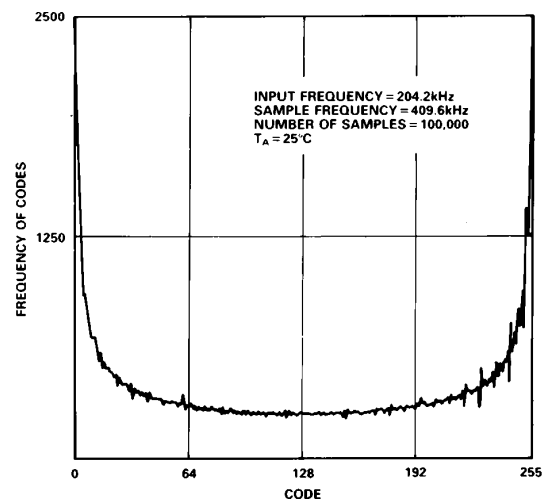


Figure 16. ADC Histogram Plot

AD7569/AD7669

INTERFACING THE AD7569/AD7669

AD7569/AD7669—Z80 INTERFACE

Figure 17 shows a typical interface to the Z80 microprocessor. The ADC is configured for operation in the Mode 1 interface mode. A precise timer or clock source starts conversion in applications requiring equidistant sampling intervals. The scheme used, whereby $\overline{\text{INT}}$ of the AD7569/AD7669 generates an interrupt on the Z80, is limited in that it does not allow the ADC to be sampled at the maximum rate. This is because the time between samples has to be long enough to allow the Z80 to service its interrupt and read data from the ADC. To overcome this, some buffer memory or FIFO could be placed between the AD7569/AD7669 and the Z80. Writing data to the relevant AD7569/AD7669 DAC simply consists of a $\langle \text{LD}(\text{nn}), \text{A} \rangle$ instruction where nn is the decoded address for that DAC. Reading data from the ADC, after an $\overline{\text{INT}}$ has been received, consists of a $\langle \text{LDA}, (\text{nn}) \rangle$ instruction.

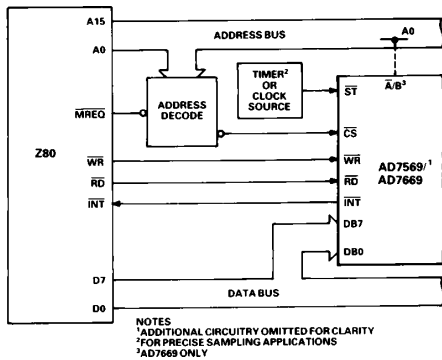


Figure 17. AD7569/AD7669 to Z80 Interface

AD7569/AD7669—68008 INTERFACE

A typical interface to the 68008 is shown in Figure 18. In this case, the ADC is configured in the Mode 2 interface mode. This means that the one read instruction starts conversion and reads the data. The read cycle is stretched out over the entire conversion period by taking the $\overline{\text{INT}}$ line back into the DTACK input of the 68008. The additional gates are required so the 68008 receives a DTACK when the processor is writing data to the AD7569/AD7669. In this case, there are no wait states introduced into the write cycle. Writing data to the relevant AD7569/AD7669 DAC consists of a $\langle \text{MOVE.B Dn}, \text{addr} \rangle$ where Dn is the data register, which contains the data to be loaded to that DAC, and addr is the decoded address for the DAC. Data is read from the ADC using a $\langle \text{MOVE.B addr}, \text{Dn} \rangle$ with the conversion result placed in register Dn.

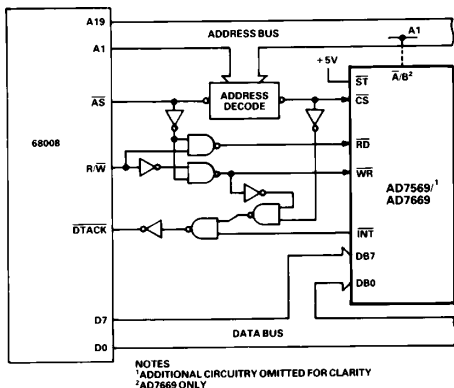


Figure 18. AD7569/AD7669 to 68008 Interface

AD7569/AD7669—ADSP-2100 INTERFACE

Figure 19 shows a typical interface to the DSP processor, the ADSP-2100. The ADC is in the Mode 2 interface mode, which means that the ADSP-2100 is halted during conversion. This is achieved using the decoded address output. This is gated with $\overline{\text{DMWR}}$ to ensure that it halts the processor for READ instructions only. $\overline{\text{INT}}$ going low at the end of conversion releases the processor and allows it to finish off the READ instruction.

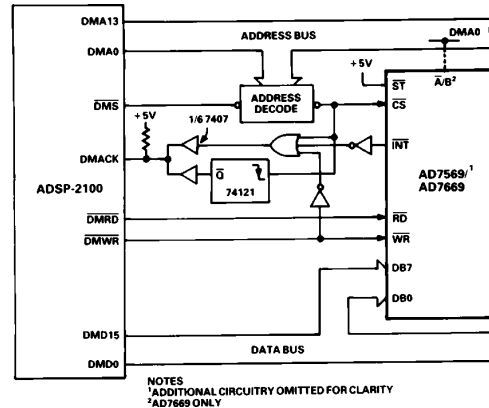


Figure 19. AD7569/AD7669 to ADSP-2100 Interface

Because the instruction cycle of the ADSP-2100 is so fast (125 ns cycle), the $\overline{\text{DMWR}}$ pulse also has to be stretched also for write cycles. This is achieved using the 74121, which generates a pulse that is fed back to DMACK. The duration of this pulse determines how long the ADSP-2100 write cycle is stretched. The buffers driving the DMACK line must have open-collector outputs. Writing data to the relevant AD7569/AD7669 DAC is achieved using a single instruction, $\langle \text{DM}(\text{addr}) = \text{MRO} \rangle$, where addr is the decoded address of that DAC, and MRO contains the data to be loaded to the DAC register. Data is read from the ADC also, using a single instruction $\langle \text{MRO} = \text{DM}(\text{addr}) \rangle$, where the conversion result is placed in the MRO data register.

AD7569/AD7669—IBM PC* INTERFACE

The AD7569/AD7669 is ideal for implementing an analog input/output port for the IBM PC. Figure 20 shows an interface that realizes this function. The ADC is configured in the Mode 1 interface mode, and conversions are initiated using a precise clock source for equidistant sampling intervals. At the end of conversion, the $\overline{\text{INT}}$ line goes low, and the 74121 generates

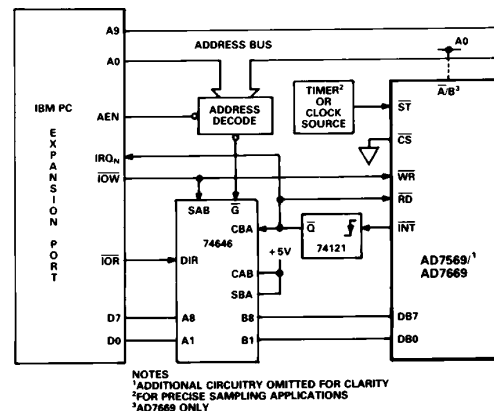


Figure 20. AD7569/AD7669 to IBM PC Interface

*IBM PC is a trademark of International Business Machines Corp.

AD7569/AD7669

APPLYING THE AD7569/AD7669 ADC

The analog input on the AD7569/AD7669 accepts the same four input ranges as the output ranges on the DAC. Whatever output range is selected for the DAC also applies to the input range of the ADC.

Although separate AGNDs exist for both the DAC and ADC to minimize crosstalk, writing data to the DAC while the ADC is performing a conversion may result in an incorrect conversion from the ADC due to an interaction of currents between the DAC and ADC. Therefore, to ensure correct operation of the ADC, the DAC register should not be updated while the ADC is converting.

UNIPOLAR OPERATION

The circuit of Figure 21 shows the AD7569 configured for both an input and output range of 0 V to +1.25 V (the AD7669 configuration is similar). The nominal transfer characteristic for this range is shown in Figure 22. The output code is Natural Binary with 1 LSB = (1.25/256)V = 4.88 mV.

As before, to achieve the unipolar 0 V to +2.5 V input range, V_{SS} is connected to 0 V, and the RANGE input is tied to a logic high. The nominal transfer characteristic is as in Figure 22 but, in this case, 1 LSB = (2.5/256)V = 9.76 mV.

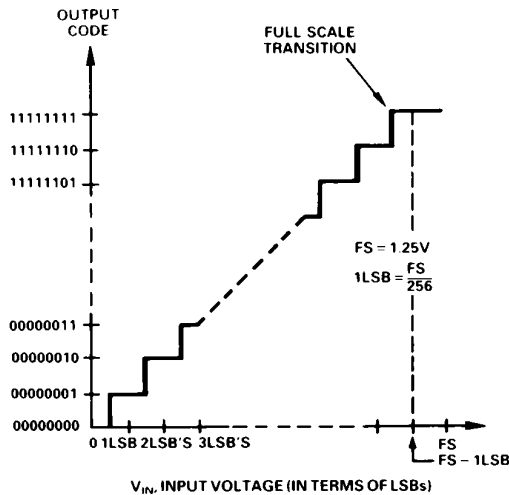


Figure 22. Nominal Transfer Characteristic for Unipolar (0 V to +1.25 V) Operation

BIPOLAR OPERATION

The analog input of the AD7569/AD7669 ADC is configured for bipolar inputs when $V_{SS} = -5$ V. The output code provided by the part is twos complement. Figure 23 shows the transfer function for bipolar (-1.25 V to +1.25 V) operation. The LSB size for this range is (2.5/256)V = 9.76 mV.

The transfer function for the -2.5 V to +2.5 V range is identical to that of Figure 23, but now FS = 5 V and the LSB size is (5/256)V = 19.5 mV.

ADC OFFSET AND FULL-SCALE ERROR ADJUSTMENT

In most Digital Signal Processing (DSP) applications, offset and full-scale error have little or no effect on system performance. A

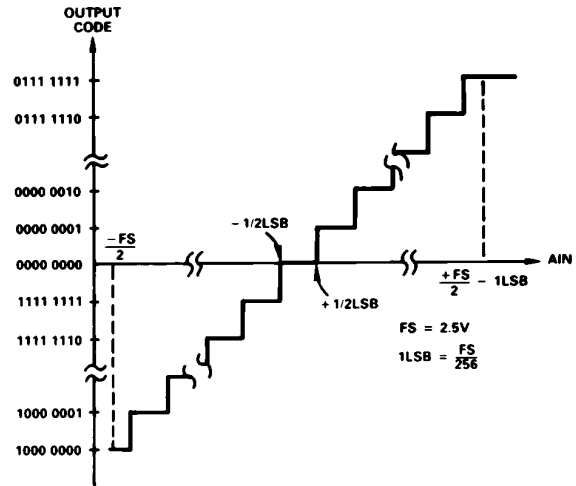
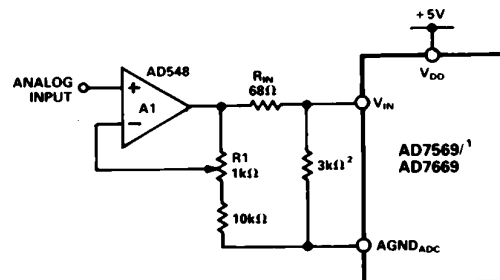


Figure 23. Nominal Transfer Characteristic for Bipolar (-1.25 V to +1.25 V) Operation

typical example is a digital filter where an ac analog signal is quantized by the ADC, digitally processed and recreated using the DAC. In these types of applications, the offset error can be eliminated by ac coupling the recreated signal. Full-scale error effect is linear and does not cause problems as long as the input signal is within the full dynamic range of the ADC. An important parameter in DSP applications is Differential Nonlinearity, and this is not affected by either offset or full-scale error.

In applications where absolute accuracy is important ADC offset and full-scale error can be adjusted to zero. Figure 24 shows the additional components required for offset and full-scale error adjustment. Offset error must be adjusted before full-scale error. Zero offset is achieved by adjusting the offset of the op amp driving V_{IN} (i.e., A1 in Figure 23). In unipolar applications, for zero offset error, apply 1/2 LSB at the analog input and adjust the op amp offset voltage until the ADC output code flickers between 0000 0000 and 0000 0001. For zero full-scale error, apply an analog input of FS - 3/2 LSBs and adjust R1 until the ADC output code flickers between 1111 1110 and 1111 1111.

In bipolar applications, to adjust for bipolar zero offset, apply -1/2 LSB at the analog input and adjust the op amp offset voltage until the output code flickers between 1111 1111 and 0000 0000. For zero full-scale error, apply +FS/2 - 3/2 LSB at the analog input and adjust R1 until the ADC output code flickers between 0111 1110 and 0111 1111.



NOTES
¹ADDITIONAL PINS OMITTED FOR CLARITY
²FOR UNIPOLAR RANGES THIS CAN BE O/C WITH $R_m = 270\Omega$

Figure 24. ADC Error Adjust Circuit

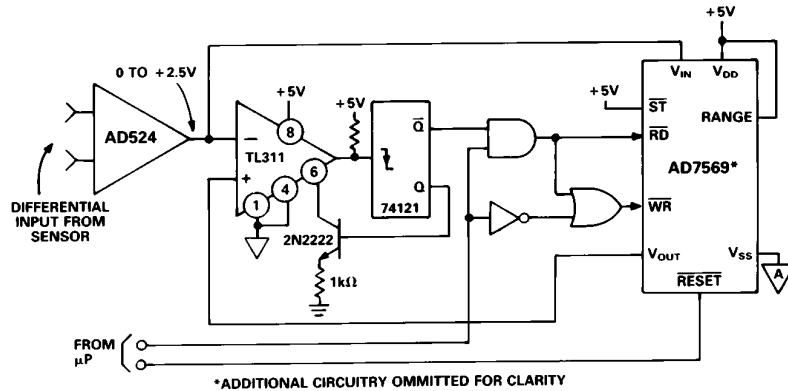


Figure 25. Peak-Reading A/D Converter

PEAK DETECTION—AD7569

The circuit of Figure 25 shows a peak-reading A/D converter, which is useful in such applications as monitoring flow rates, temperature, pressure, etc. The circuit ensures that a peak will not be missed while at the same time does not require the microprocessor to frequently monitor the data. The peak value is stored in the A/D converter and can be read at any time.

The gain on the AD524 is adjusted to yield a 0 V to +2.5 V output. When the input signal exceeds the current stored value, the output of the TL311 goes low, triggering the \bar{Q} output of the 74121. This low-going pulse starts a conversion on the AD7569 ADC, and at the end of conversion latches the result into the DAC. This pulse must be at least 120 ns greater than the conversion time of the ADC. The Q output is used to drive the strobe input of the TL311, resetting the TL311 output high in readiness for another conversion.

The additional gates on the \bar{RD} and \bar{WR} inputs are to allow the data to be read by the microprocessor while at the same time ensuring that the DAC is not updated when the microprocessor reads the data. It may be necessary to monitor the AD7569 \overline{BUSY} line to ensure that a processor READ is not attempted while the AD7569 is in the middle of a conversion. The READ pulse width from the processor must be less than 1 μ s to ensure correct data is read from the ADC. A low-going pulse on the RESET line resets the DAC output to 0 V and starts a new "peak-detection" period. This RESET pulse must also be less than 1 μ s.

DISK DRIVE APPLICATION—AD7669

Closed-Loop Microstepping

Microstepping is a popular technique in low density disk drives (both floppy and hard disk) that allows higher positional resolution of the disk drive head over that obtainable from a full-step driven stepper motor. Typically, a two-phase stepper motor has its phase currents driven with a sine-cosine relationship. These cosinusoidal signals are generated by two DACs driven with the appropriate data. The resolution of the DACs determines the number of microsteps into which each full step can be divided. For example, with a 1.8° full-step motor and a 4-bit DAC, a microstep size of 0.11° ($1.8^\circ/(2^4)$) is obtainable.

The microstepping technique improves the positioning resolution possible in any control application; however, the positional accuracy can be significantly worse than that offered by the original full-step accuracy specification due to load torque effects.

To ensure that the increased resolution is usable, it is necessary to use a closed-loop system where the position of the disk drive

head (or motor) is monitored. The closed-loop system allows an error between the desired position and the actual position to be monitored and corrected. The correction is achieved by adjusting the ratio of the phase currents in the motor windings until the required head position is reached.

The AD7669 is ideally suited for the closed-loop microstepping technique with its on-chip dual DACs for positioning the disk drive head, and onboard ADC for monitoring the position of the head. A generalized circuit for a closed-loop microstepping system is shown in Figure 26. The DAC waveforms are shown in Figure 27, along with the direction information for clockwise rotation supplied by the controller.

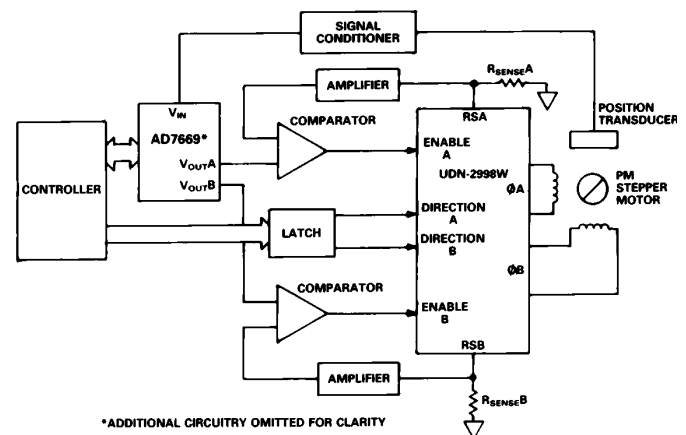


Figure 26. Typical Closed-Loop Microstepping Circuit with the AD7669

The AD7669 is used in the unipolar 0 V to +2.5 V configuration. This allows the circuit of Figure 26 to be completely unipolar (+5 V, +12 V supplies); no negative power supplies are required. The power output stage is a dual H-Bridge device such as the UDN-2998W from Sprague Electric. The phase currents in both windings are detected by means of the small value sense resistors, $R_{S(A)}$ and $R_{S(B)}$, in series with the windings. The voltage developed across these resistors is amplified and compared with the respective DAC output voltage. The comparators in turn chop the phase winding current. The ADC completes the feedback path by converting information from a suitable transducer for analysis by the controller.

AD7569/AD7669

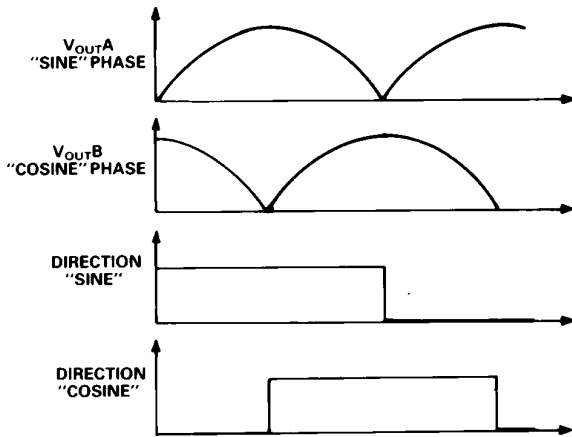


Figure 27. Typical DAC Output Voltages for Microstepping and Direction Signals for Clockwise Rotation with the UDN-2998W

ANALOG DELAY LINE—AD7569

In many applications, especially in audio systems, it is necessary to provide a delay on the input signal. The circuit of Figure 28 shows how a simple analog delay line can be implemented, based on the AD7569. The input signal is sampled using the AD7569 ADC, and converted data is loaded into the 6116 (2K × 8 static ram). The inverted input clock drives a counter that selects the address for the 6116. The delay is selected by choosing one of the output lines of the HCT4040 counter to reset the counter. This can be done using a simple switch in a manual system or by a multiplexer in a programmable delay application. Data is written to the DAC using the inverted input clock signal.

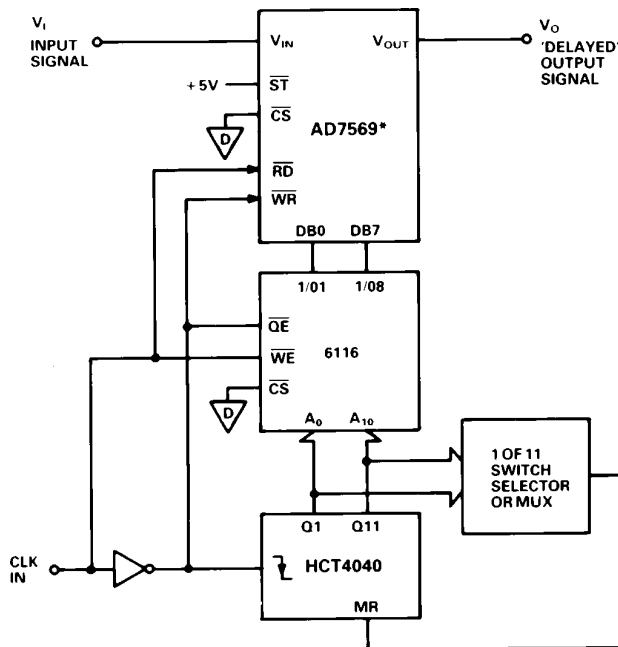


Figure 28. Analog Delay Line

On initial start-up, the output voltage, V_o , will be invalid until the length of the delay is reached (i.e., until the counter is reset). From this point forward, the delayed data is read from the 6116 and loaded to the DAC before the newly converted data is written into the same memory location. The input clock to the system can be a square wave of maximum input frequency 200 kHz

(assuming 2 μ s conversion time for the ADC). The mark/space ratio of the input clock can be varied to maximize the sampling frequency if required. The clock low time has to be equal to the conversion time and access time of the ADC plus the setup time required for the 6116. The clock high time has only to be equal to the setup time for the DAC plus the delay time through the counter and the access time of the 6116.

The amount of memory used, as well as the sampling frequency, determines the maximum possible delay. Using the HCT4040, and the 6116 with an input clock frequency of 200 kHz, the maximum delay is 5 ms on a maximum input frequency of 100 kHz. Using 64K memory, with an 8 kHz input clock frequency, the maximum delay is 8 seconds on a maximum input frequency of 4 kHz.

TRANSIENT RECORDER—AD7569

The scheme just outlined can also form the basis for a transient recorder. In this case, transients on the input signal are converted and stored in memory. The transient can then be recalled from memory at a later time, and the transient waveform can be recreated using the AD7569 DAC.

INFINITE SAMPLE-AND-HOLD—AD7569

The AD7569 is ideal for implementing a single-chip infinite sample-and-hold function. Basically, the ADC samples and converts the input signal into an 8-bit digital word. The 8 bits of data are then loaded to the DAC and the sampled value is stored to analog form. The sampled value is held until the DAC register is updated. The full-scale matching between the ADC and the DAC on the AD7569 ensures a typical error of less than 1% between the analog input voltage and the "held" output voltage. Figure 29 shows the connections required on the AD7569 to achieve this infinite sample-and-hold function.

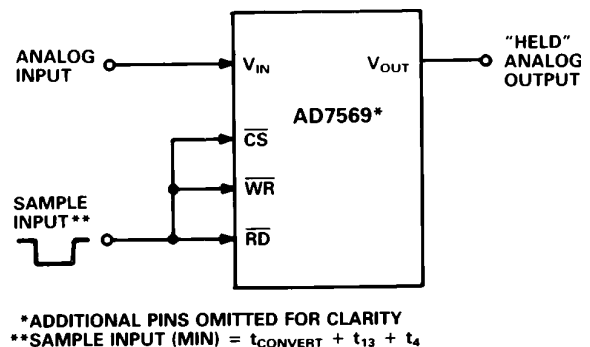


Figure 29. Infinite Sample-and-Hold

TARE FUNCTION FOR WEIGH SCALE—AD7569

The infinite sample-and-hold just outlined can also form the basis of a circuit to provide a tare function for a weigh scale system. Figure 30 shows a circuit for a weigh scale system. It incorporates a tare function using a simple circuit based on the AD7569.

The AD587, along with the 2N6285, provides a buffered +10 V reference to supply the low impedance load cell transducer. The load cell output is amplified by the AD624 precision instrumentation amplifier with gain adjustment provided by R1. The output of the AD624 is applied to the noninverting input of a unity gain differential summing amplifier that uses the AD707, a high precision op amp with low drift. The AD707 feeds a 3 1/2 digit

panel meter module that converts the signal for digital readout. The input signal to the panel meter is also applied to the analog input of the AD7569 for the tare function. When the tare switch (S1) is closed, a tare cycle commences and V_{IN} is sampled and held infinitely at V_{OUT} until the next tare cycle. V_{OUT} drives the inverting input of the differential amplifier and forces its output to zero. Thus, the tare function is used to give a readout of zero for any undesired weight, such as a box, when only the item placed in it is to be weighed. The tare function can also be used in calibrating the system, to cancel out offset errors due to the load cell, AD624 and differential amplifier.

The AD7569 offers many advantages in the system outlined, such as: simple, low cost circuit—no need for microprocessor, software, etc.—and low power consumption.

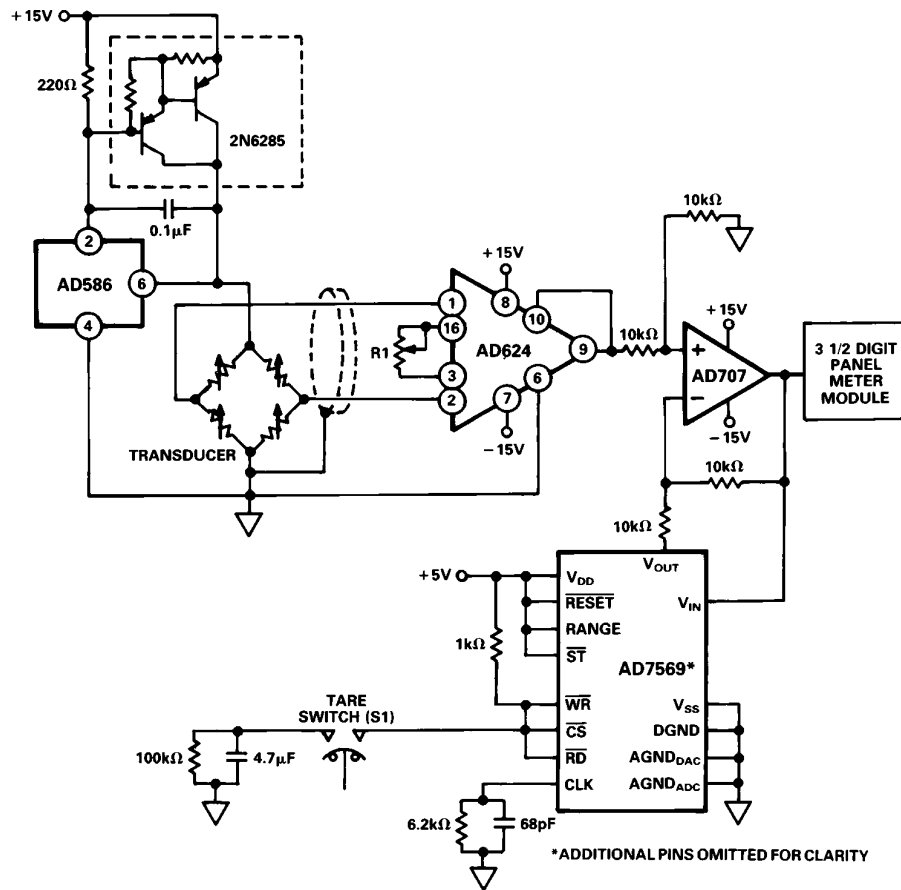


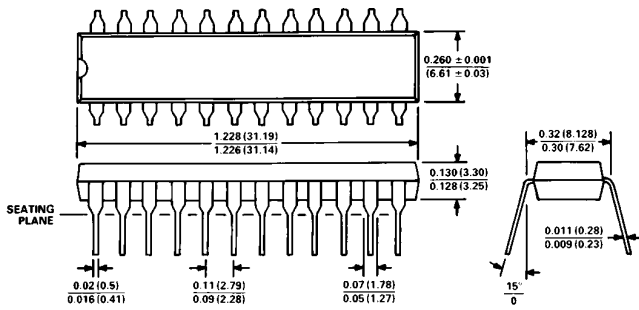
Figure 30. Weigh Scale System with Tare Function

AD7569/AD7669

OUTLINE DIMENSIONS

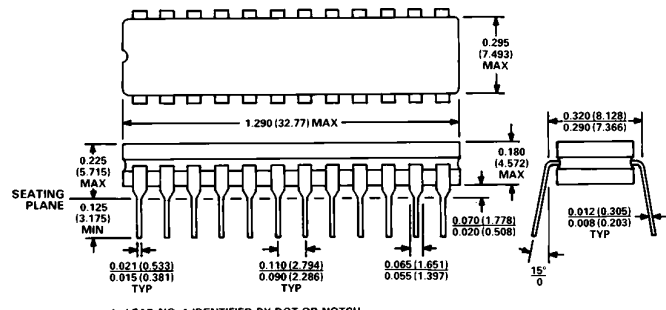
Dimensions shown in inches and (mm).

24-Pin Plastic (N-24)



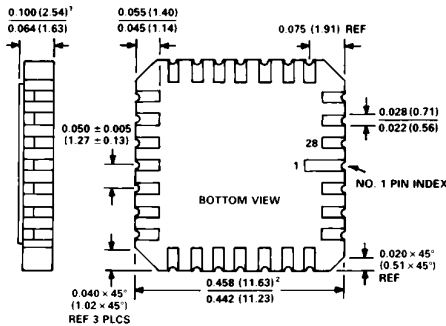
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 1. LEAD NO. 1 IDENTIFIED BY DOT OR NOTCH.
 2. PLASTIC LEADS WILL BE EITHER SOLDER DIPPED OR TIN LEAD PLATED IN ACCORDANCE WITH MIL-M-38510 REQUIREMENTS.

24-Pin Cerdip (Q-24)



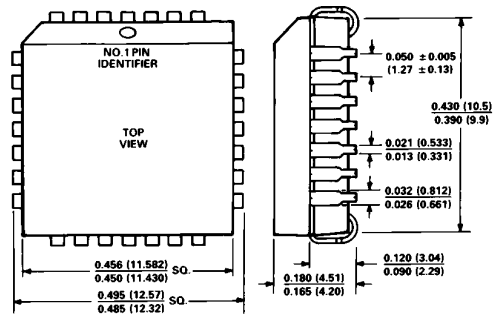
1. LEAD NO. 1 IDENTIFIED BY DOT OR NOTCH.
 2. CERDIP LEADS WILL BE EITHER TIN PLATED OR SOLDER DIPPED IN ACCORDANCE WITH MIL-M-38510 REQUIREMENTS.

28-Terminal Leadless Ceramic Chip Carrier (E-28A)

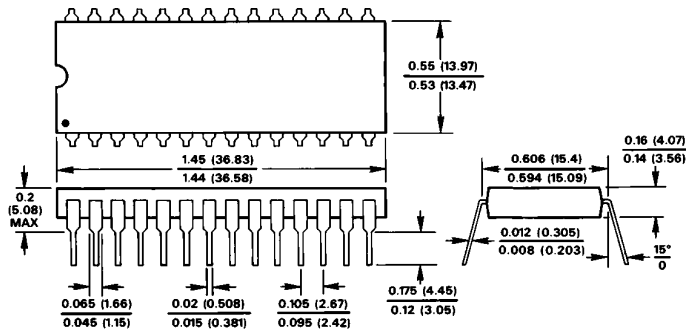


- NOTES
 1. THIS DIMENSION CONTROLS THE OVERALL PACKAGE THICKNESS.
 2. APPLIES TO ALL FOUR SIDES.
 ALL TERMINALS ARE GOLD PLATED.

28-Terminal Plastic Ledged Chip Carrier (P-28A)



28-Pin Plastic DIP (N-28)



- LEAD NO. 1 IDENTIFIED BY DOT OR NOTCH
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28-Lead Small Outline (SO) (R-28)

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